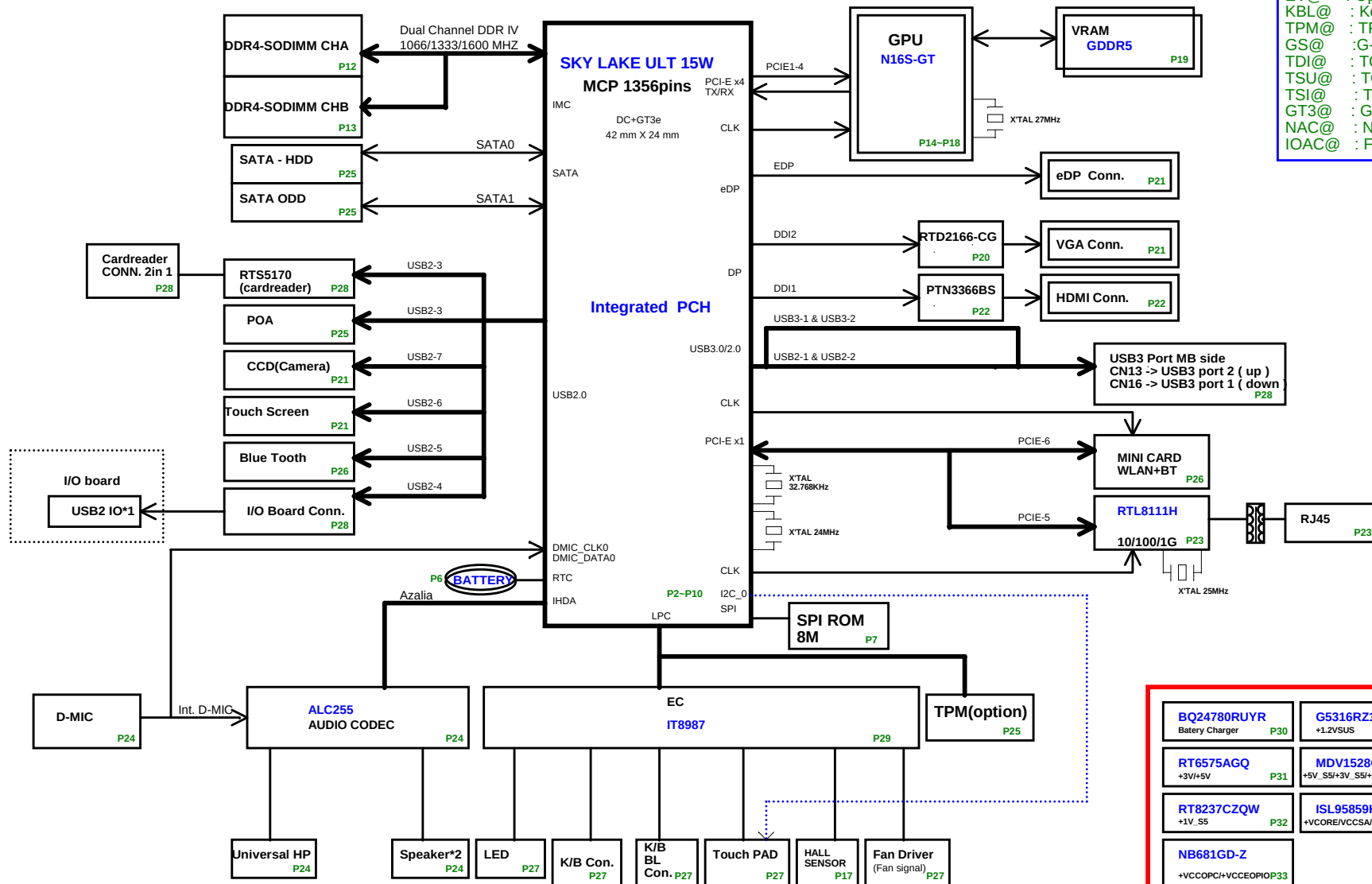


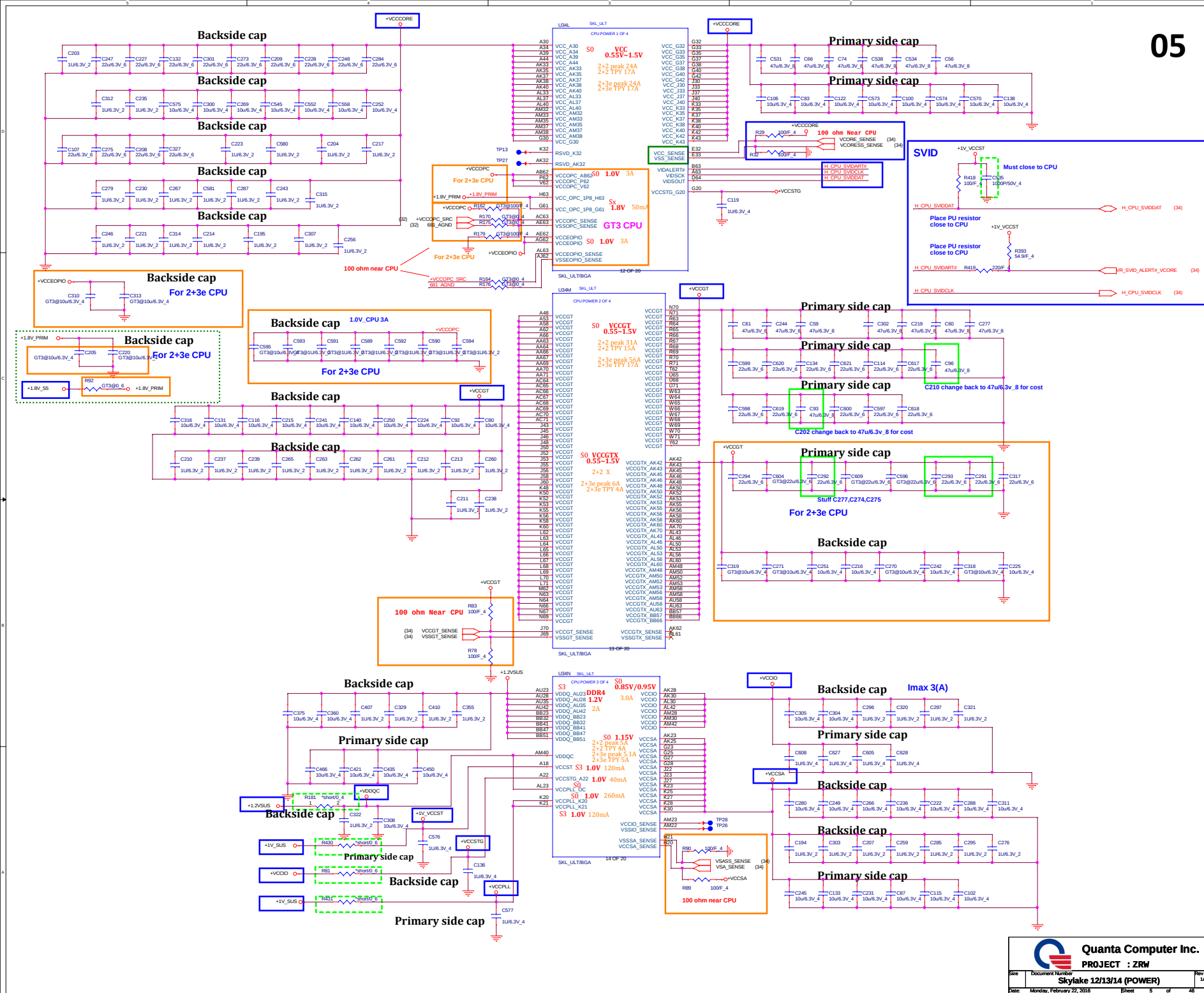
Z8V Serials SKL ULT SYSTEM BLOCK DIAGRAM

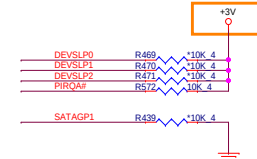
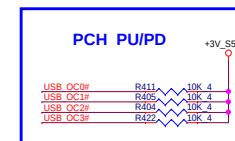


BOM

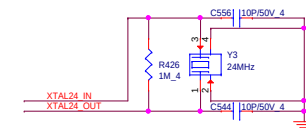
IV@ : iGPU
 EV@ : Optimus
 KBL@ : Keyboard backlight
 TPM@ : TPM
 GS@ : G-SENSOR
 TDI@ : TOUCH PAD I2C
 TSU@ : TOUCH SCREEN USB
 TSI@ : TOUCH SCREEN I2C
 GT3@ : GT3 CPU
 NAC@ : Non IOAC
 IOAC@ : For IOAC

BQ24780RUYR Battery Charger P30	G5316RZ1D +1.2VSUS P34	Thermal Protection Discharger P38
RT6575AGQ +3V/+5V P31	MDV1528Q +5V_S5/+3V_S5/+3V/+5V P31	UP1658RQKF +VGPU CORE P39
RT8237CZQW +1V_S5 P32	ISL95859HRTZ-T +VCORE/VCCSA/VCCGT P35	RT8068AZQW +1.05V_GFX/+3V_GFX +1.5V_GFX P40
NB681GD-Z +VCCOPCI/+VCCOPROP33		





Skylake-U used 24 MHz (50 Ohm ESR) XTAL

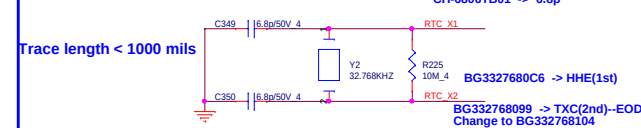


BG624000078 -> HHE(1st)
BG624000044 -> TXC(2nd)

Note: Change Y4 to 38.4 MHz(ESR 30 ohm) for Cannonlake U

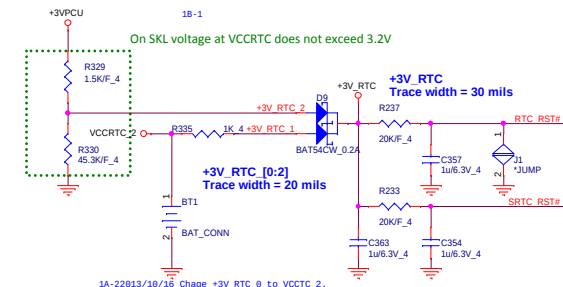
RTC Clock 32.768KHz (RTC)

CH01006JB08 -> 10p
CH01506JB06 -> 15p
CH-6806TB01 -> 6.8p

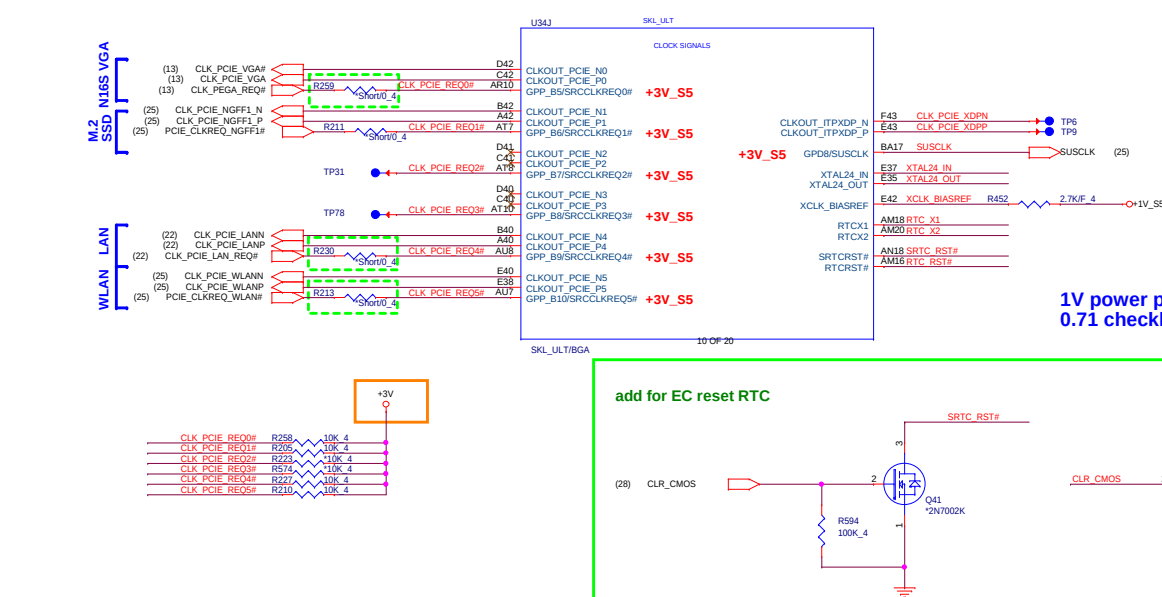


RTC Circuitry (RTC)

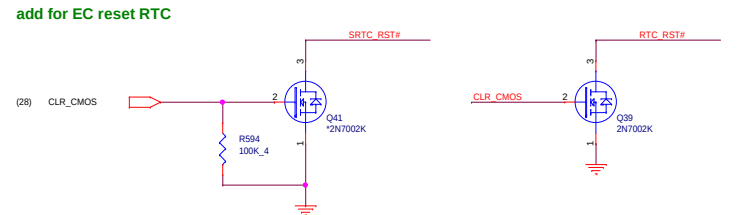
On SKL voltage at VCCRTC does not exceed 3.2V

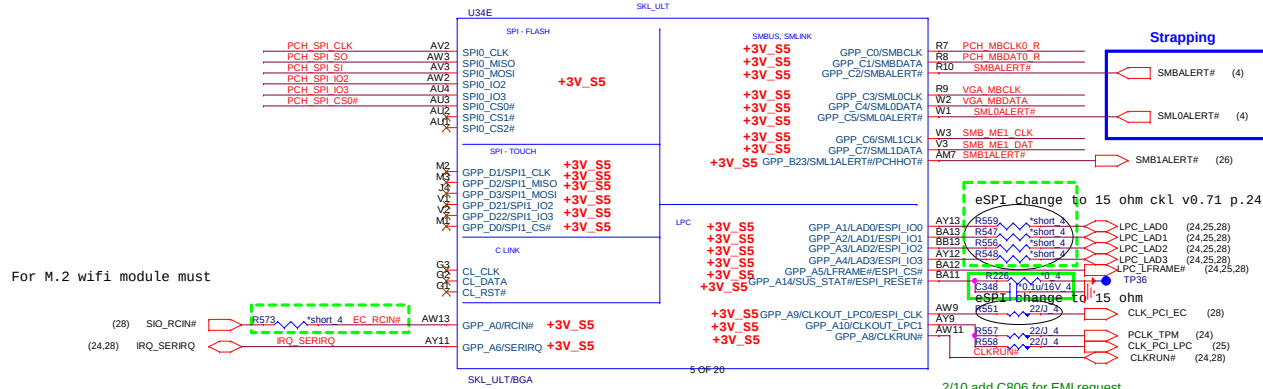


1. AHL03003057 DBV CR2032
2. AHL03003003 VDE CR2032



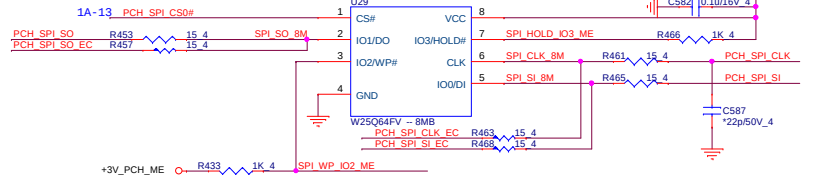
1V power plane
0.71 checklist p14





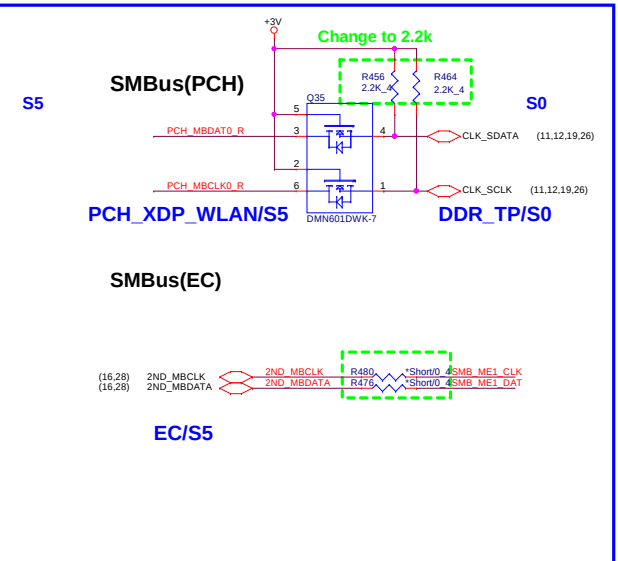
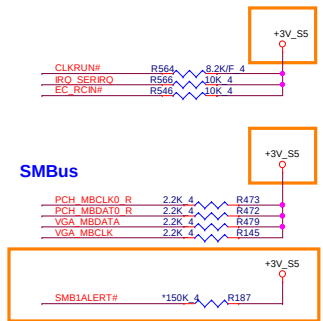
PCH SPI ROM(8M)
15ohm CS01502JB12
33ohm CS03302JB29

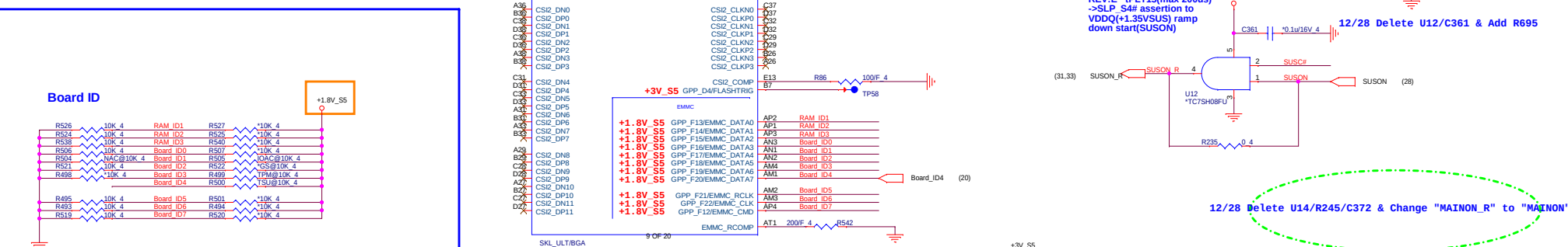
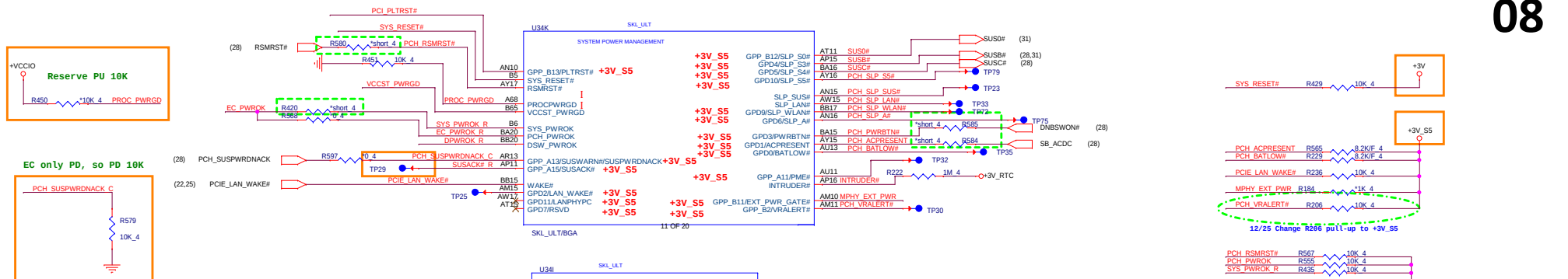
(28) PCH_SPI_CLK_EC
(28) PCH_SPI_SI_EC
(28) PCH_SPI_SO_EC



SP@ socket P/N: DFHS08FS023 only for A-TEST

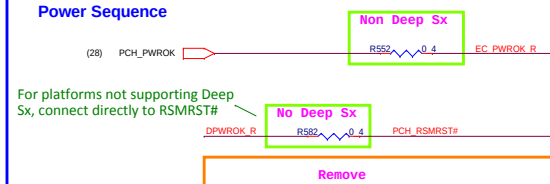
SPI ROM	Vender	Size	Quanta P/N	Vender P/N
Skylake 3.3V	WND	8M	AKE3EFP0N07	W25Q64FVSSIQ
	GGD	8M	AKE2EZNOQ00	GD25B64CSIGR



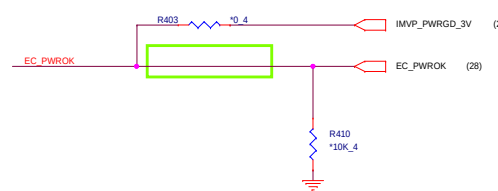


	Low	High		Low	High
BOARD_ID0	VRAM X32 (R506)	VRAM X16 (R507)	BOARD_ID5	For 14" (R495)	For 15" / 17" (R501)
BOARD_ID1	Non IOAC (R504)	IOAC (R505)	BOARD_ID6	Reserved (Default)	Reserve
BOARD_ID2	Non G-sensor (R521)	G-sensor (R522)	BOARD_ID7	Reserved (Default)	Reserve
BOARD_ID3	No TPM (R498)	TPM (R499)			
BOARD_ID4	No-Touch panel	Touch panel (R500)			

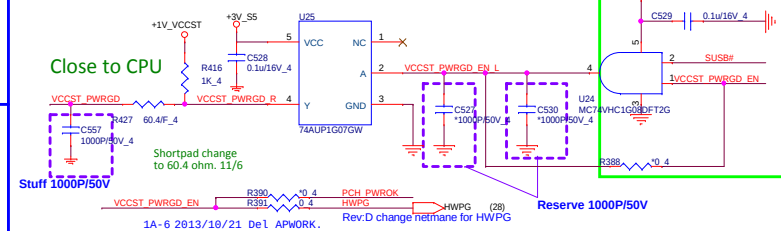
Power Sequence



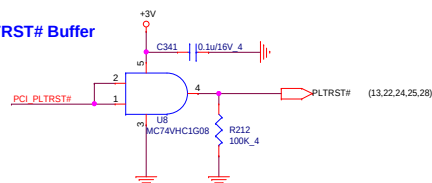
SYSPWOK



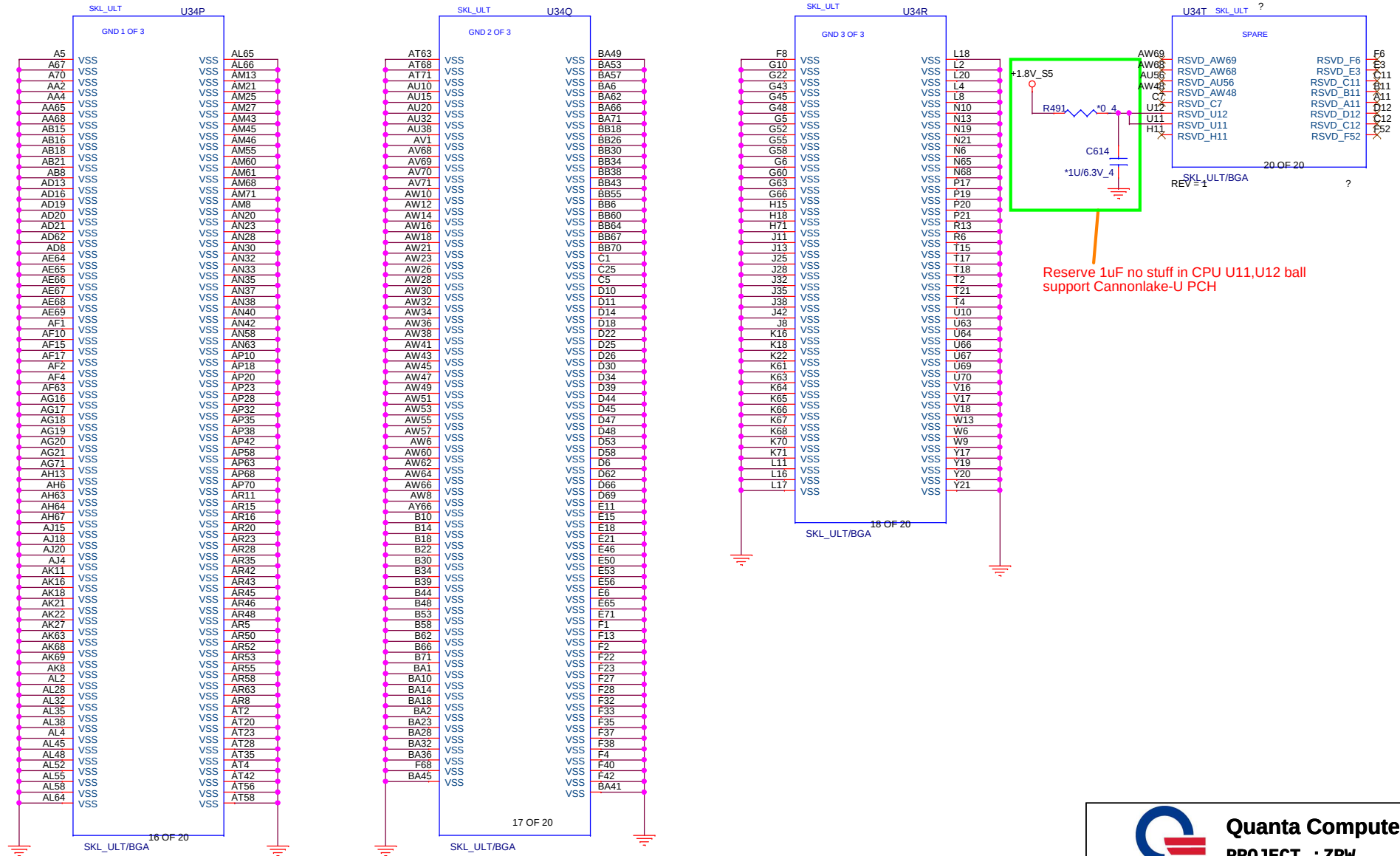
VCCST_PWRGD CRB is via +1.05V PG



PLTRST# Buffer

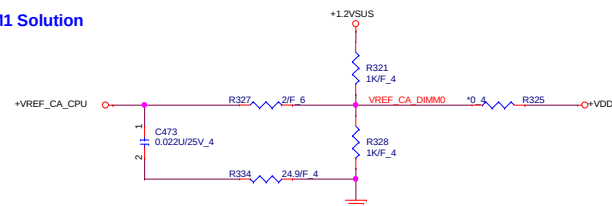


Skylake ULT (GND)



Quanta Computer Inc.
PROJECT : ZRW

Size	Document Number	Rev
	Skylake 10/17/18 (GND)	1A
Date:	Monday, February 22, 2016	Sheet 10 of 46

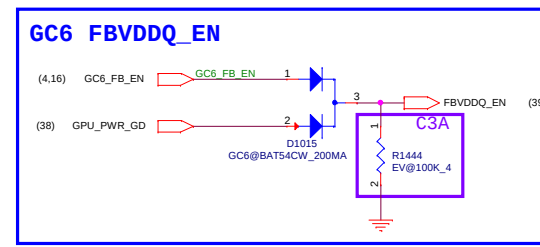


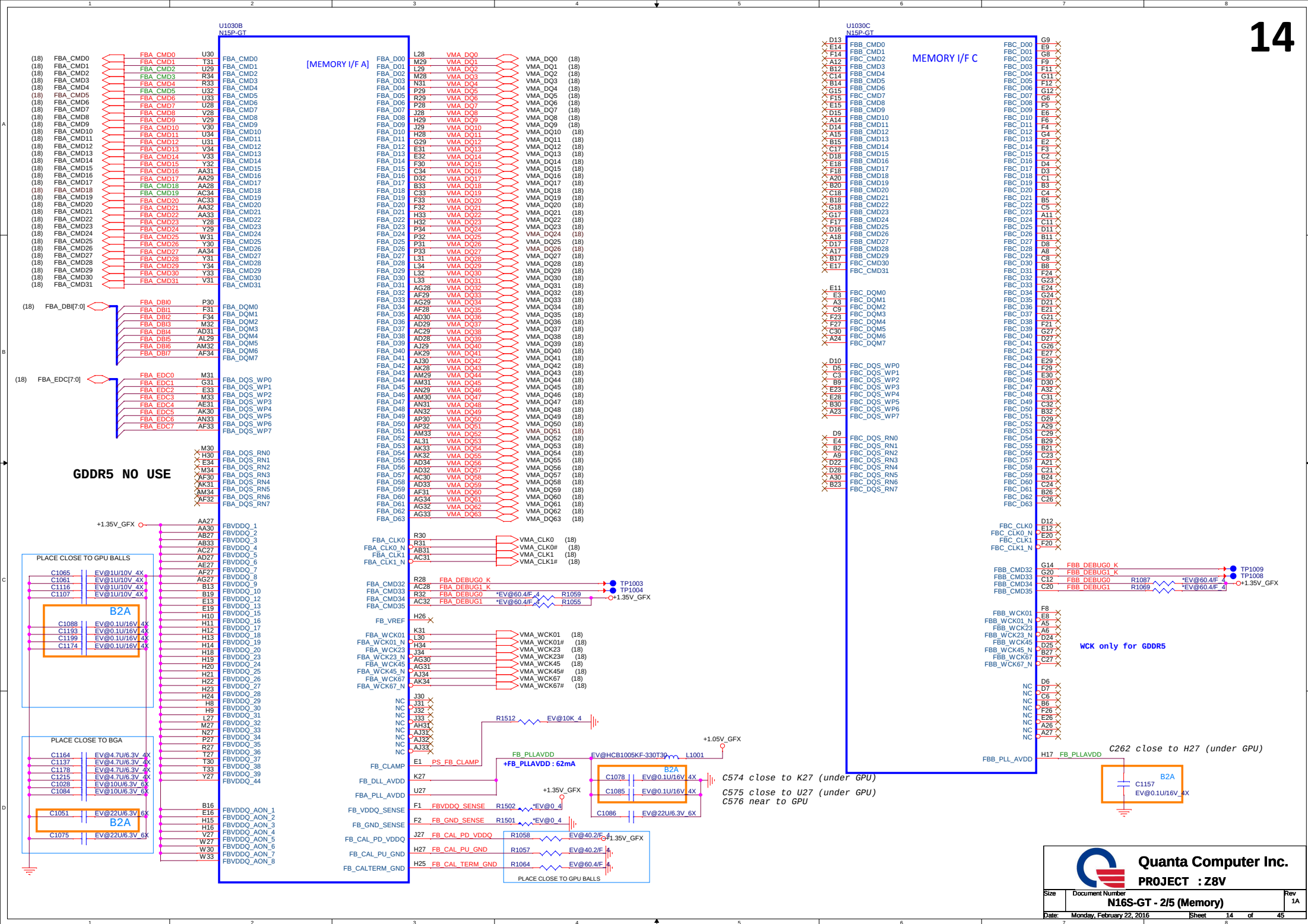
1uF/10uF 4pcs on each side of connector

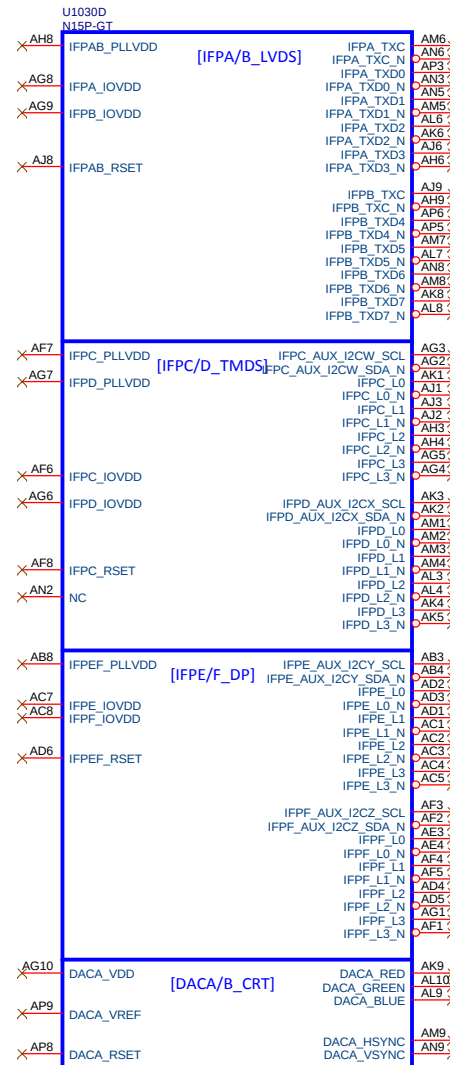


E 4pcs on each side of connector

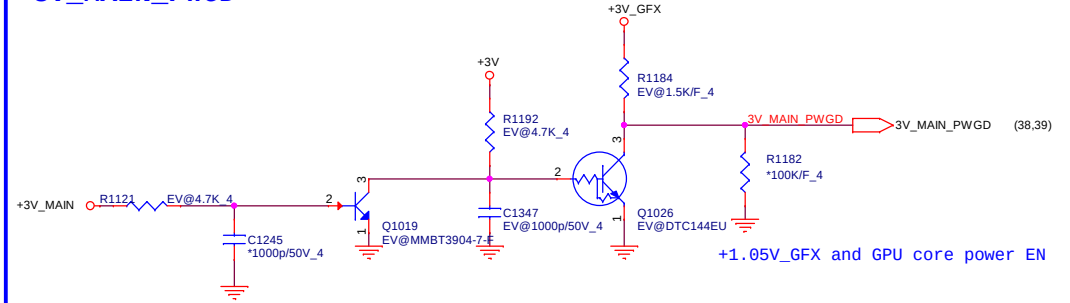
+1.2VSUS +VDDQ_VTT



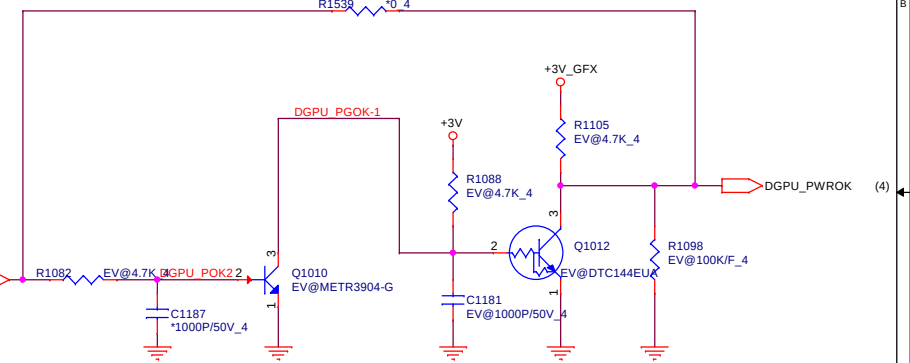




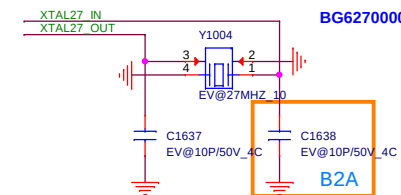
3V_MAIN_PWGD



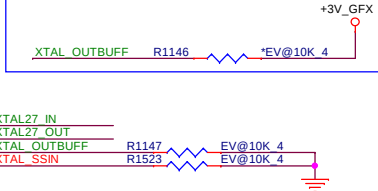
2/16 Reserve R1539 for DGPU_PWR0K doesn't have any sequence requirement



BG627000039 -> HHE(1st)
BG627000035 -> TXC(2nd)

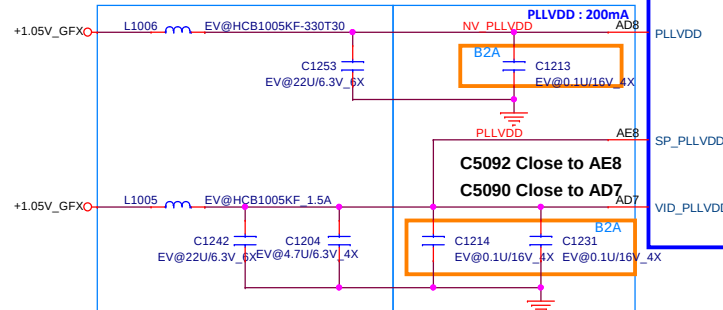


Reserve



PLACE CLOSE TO GPU

PLACE CLOSE TO BALLS



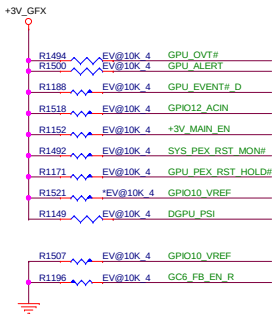
Quanta Computer Inc.
PROJECT : Z8V

Resistor P/N
 4.99K--> CS24992FB26
 10K --> CS31002FB26
 15K --> CS31502FB24
 20K --> CS32002FB29
 24.9K-->CS32492FB16
 30.1K -->CS33012FB18
 34.8K--> CS3482FB22
 45.3K --> CS34532FB18 GM
 49.9K --> CS34992FB10 GT

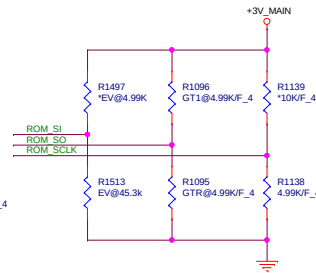
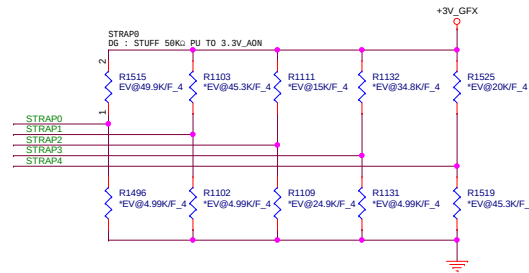
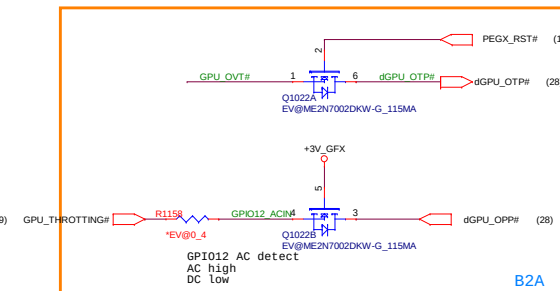
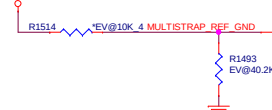
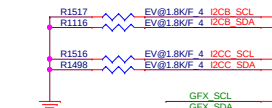
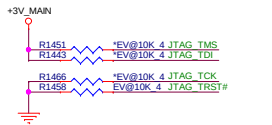
U1030E
 N16S-GT

[MIOA]

[MIOB]



Reserve PU/PD for Debug



	PU +3V_MAIN	PD
4.99K	1000	0000
10K	1001	0001
15K	1010	0010
20K	1011	0011
24.9K	1100	0100
30.1K	1101	0101
34.8K	1110	0110
45.3K	1111	0111

Mutil-level mode strapping:

For N16S-GT1-KB-A2 :
 R490=40.2k PD
 1.ROM_SCLK = 4.99K PD
 2.ROM_SO = 4.99K PU (N16S-GTR = 4.99KPD)
 3.ROM_SI= Memory strap setting
 4.STRAP0 = 49.9k PU
 5.Strap4~1 = Reserve Pull up and Pull down

	N16S-GT1-KB-A2	N16S-GTR
ROM_SO	R93 PU 4.99K	R92 PD 4.99K
ROM_SI	As below configuration table	

N16S-GT1-KB-A2 VRAM Configuration Table:

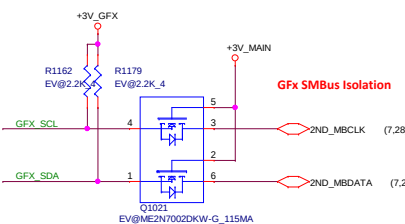
	ROM_SI	DESCRIPTION	Vendor	Vendor PIN	STN PIN	ROM_SI
4GbX2 (1GB)	0011 (0x3) 0110 (0x6)	GDDR5 128MBx32,2500MHz GDDR5 128MBx32,2500MHz	SAMSUNG HYNIX	K4G41325FC-HC03 --C die H56C4H24AJR-T2C --A die	AKG5PGDT505 AKG5PWUTW21	20K Pull down 34.8K Pull down
4GbX4 (2GB)	0011 (0x3) 0110 (0x6)	GDDR5 256MBx16,2500MHz GDDR5 256MBx16,2500MHz	SAMSUNG HYNIX	K4G41325FC-HC03 --C die H56C4H24AJR-T2C --A die	AKG5PGDT505 AKG5PWUTW21	20K Pull down 34.8K Pull down
8GbX2 (2GB)	0000 (0x0) 0001 (0x1)	GDDR5 256MBx32,2500MHz GDDR5 256MBx32,2500MHz	SAMSUNG MICRON	K4G80325FB-HC03 --B die MT51J256M32HF-60:A--A die	AKG5OGDT502 AKG5LGUTL04	4.99K Pull up 10K Pull up
8GbX4 (4GB)	0000 (0x0) 0001 (0x1)	GDDR5 512MBx16,2500MHz GDDR5 512MBx16,2500MHz	SAMSUNG MICRON	K4G80325FB-HC03 --B die MT51J256M32HF-60:A--A die	AKG5OGDT502 AKG5LGUTL04	4.99K Pull up 10K Pull up

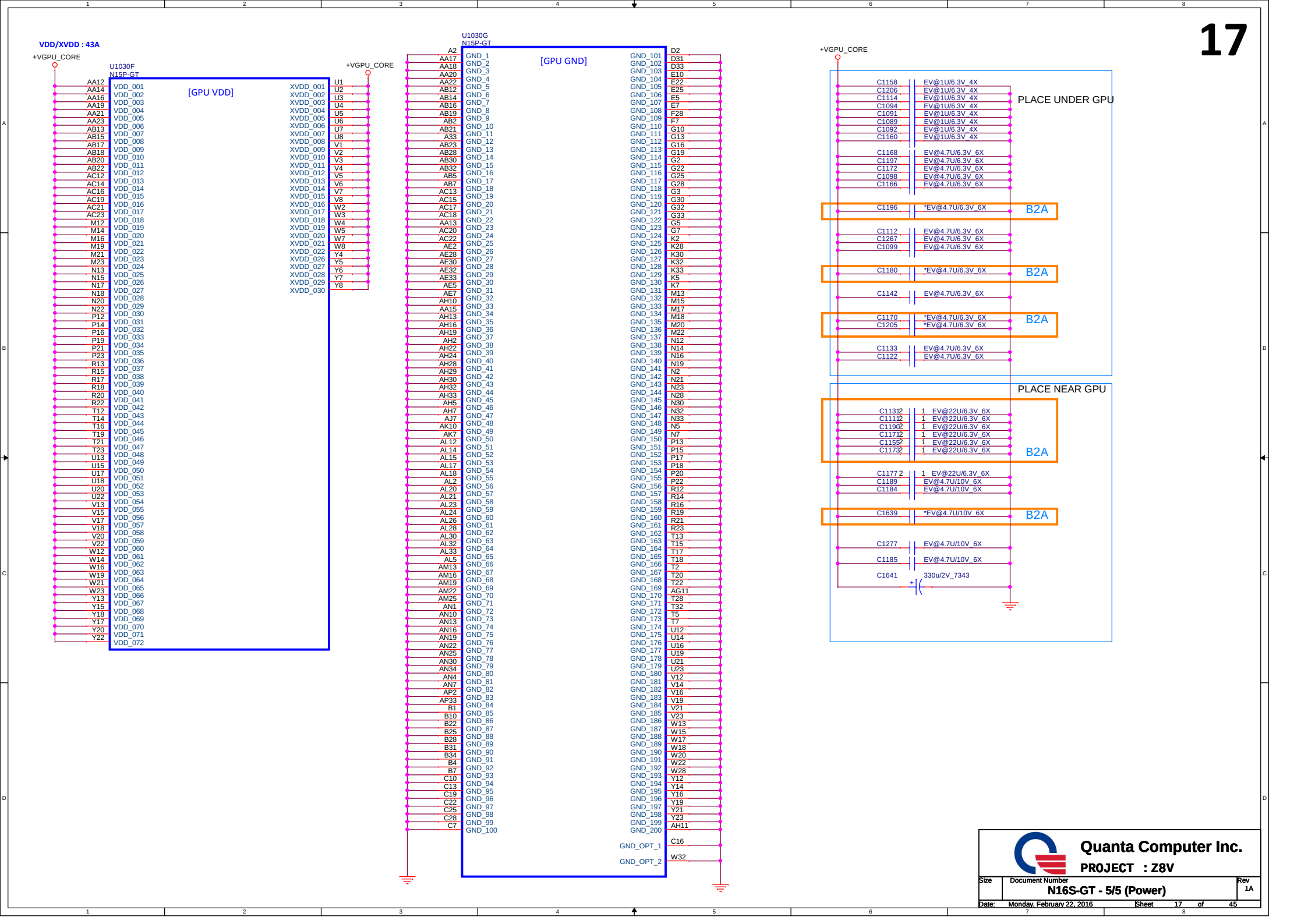
N16S-GTR VRAM Configuration Table:

	ROM_SI	DESCRIPTION	Vendor	Vendor PIN	STN PIN	ROM_SI
4GbX2 (1GB)	0011 (0x3) 0110 (0x6)	GDDR5 128MBx32,2500MHz GDDR5 128MBx32,2500MHz	SAMSUNG HYNIX	K4G41325FC-HC03 --C die H56C4H24AJR-T2C --A die	AKG5PGDT505 AKG5PWUTW21	20K Pull down 34.8K Pull down
4GbX4 (2GB)	0011 (0x3) 0110 (0x6)	GDDR5 256MBx16,2500MHz GDDR5 256MBx16,2500MHz	SAMSUNG HYNIX	K4G41325FC-HC03 --C die H56C4H24AJR-T2C --A die	AKG5PGDT505 AKG5PWUTW21	20K Pull down 34.8K Pull down
8GbX2 (2GB)	0000 (0x0) 0001 (0x1)	GDDR5 256MBx32,2500MHz GDDR5 256MBx32,2500MHz	SAMSUNG MICRON	K4G80325FB-HC03 --B die MT51J256M32HF-60:A--A die	AKG5OGDT502 AKG5LGUTL04	4.99K Pull down 10K Pull down
8GbX4 (4GB)	0000 (0x0) 0001 (0x1)	GDDR5 512MBx16,2500MHz GDDR5 512MBx16,2500MHz	SAMSUNG MICRON	K4G80325FB-HC03 --B die MT51J256M32HF-60:A--A die	AKG5OGDT502 AKG5LGUTL04	4.99K Pull down 10K Pull down

N16S-GT1-KB-A2 (GB4b-128)

	Logical Strapping Bit3	Logical Strapping Bit2	Logical Strapping Bit1	Logical Strapping Bit0	
ROM_SCLK	SOR3_EXPOSED	SOR2_EXPOSED	SOR1_EXPOSED	SOR0_EXPOSED	0000
ROM_SI	RAMCFG[3]	RAMCFG[2]	RAMCFG[1]	RAMCFG[0]	XXXX
ROM_SO	DEVID_SEL	PCIE_CFG	SMB_ALT_ADDR	VGA_DEVICE	0000
STRAP0	Keep footprint to PU to 3V3_AON and PD to GND [Stuff 49.9K PU]				0001
STRAP1	Keep footprint to PU to 3V3_AON and PD to GND [Do Not Stuff]				
STRAP2					
STRAP3					
STRAP4					





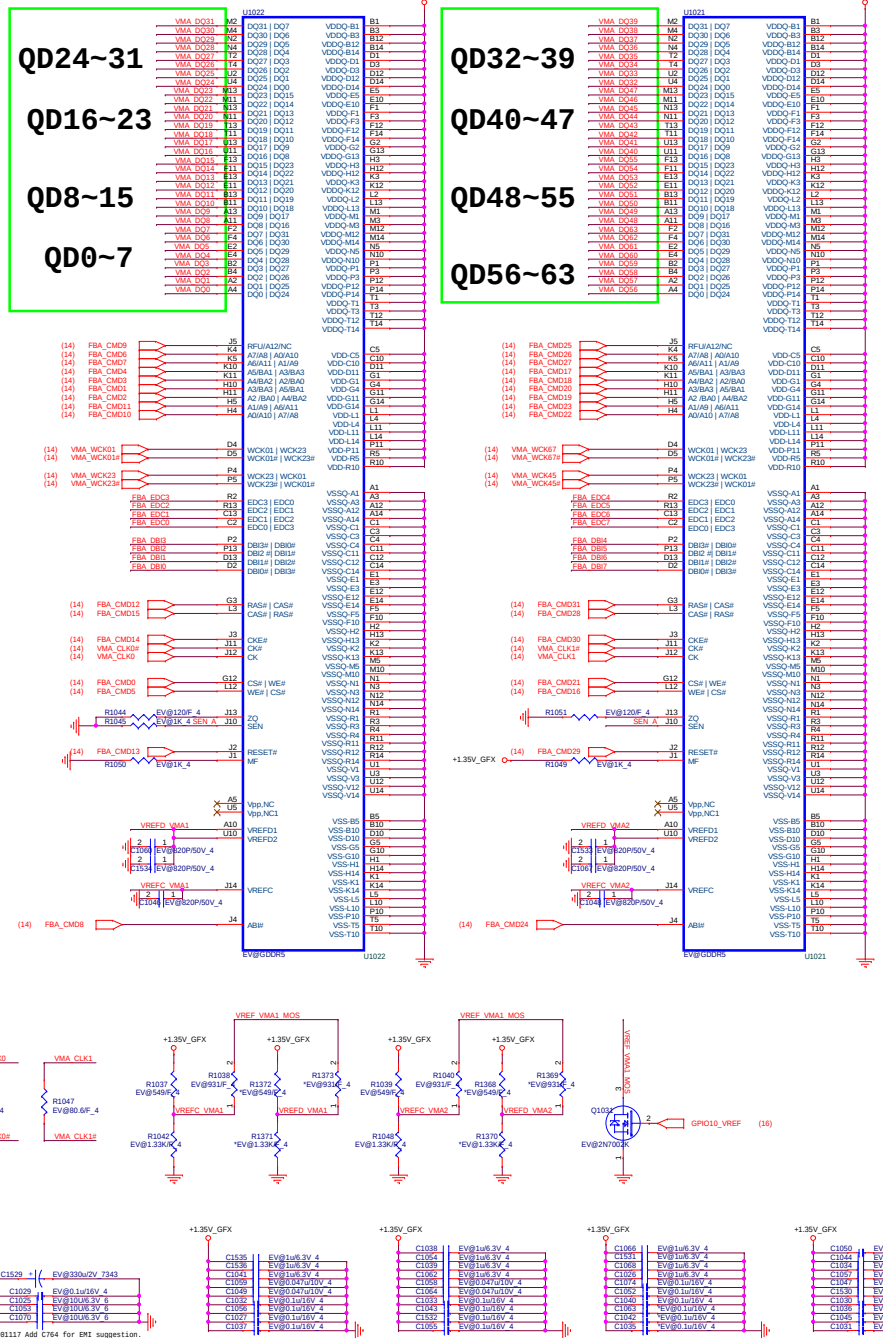
Channel 0
<0-31>

LOWER HALF

Channel 0
<32-63>

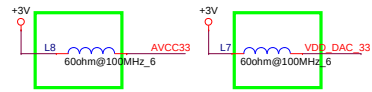
MF=0 Non-mirrored

MF=1 mirrored

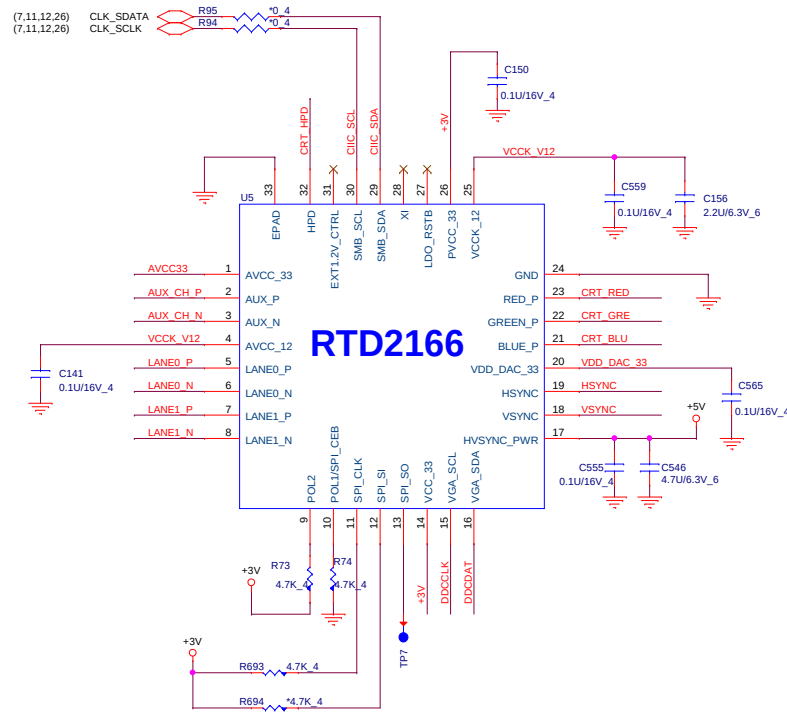
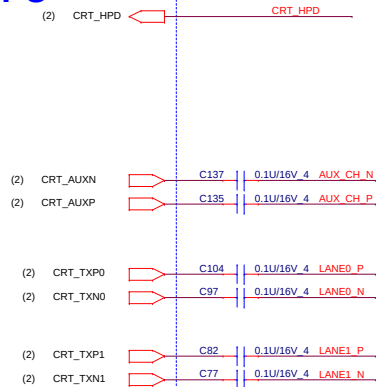


DP TO VGA

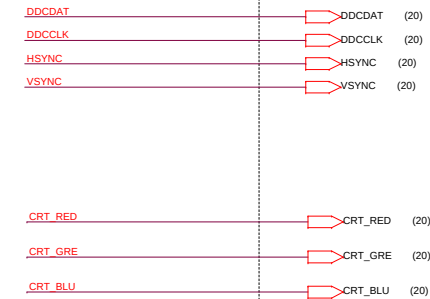
Power



CPU



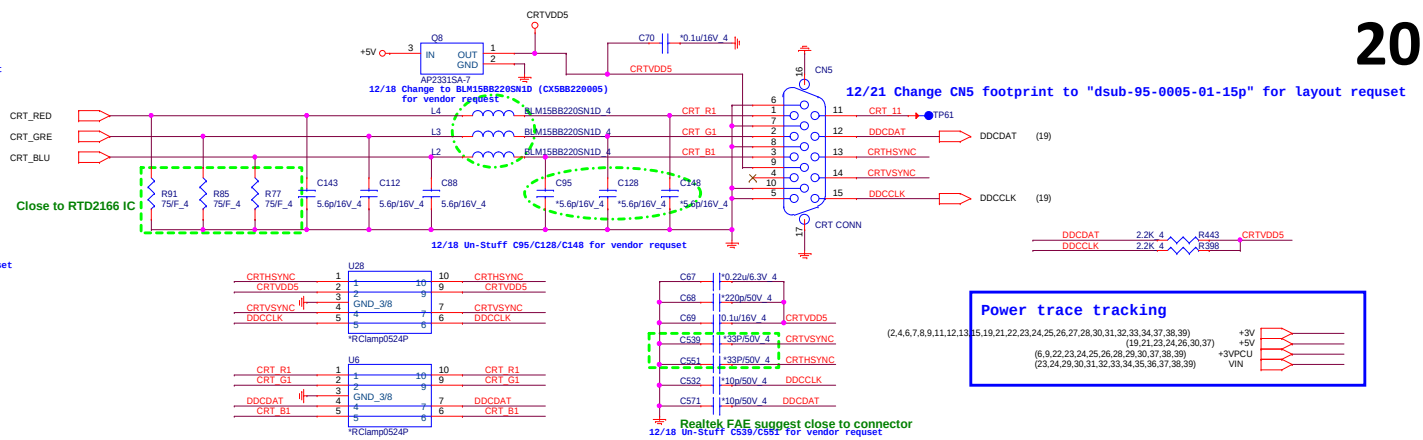
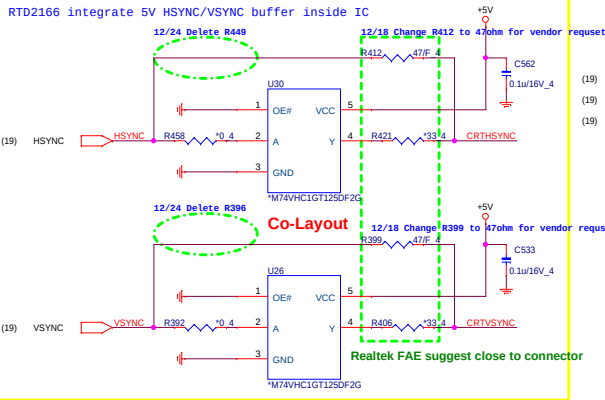
VGA



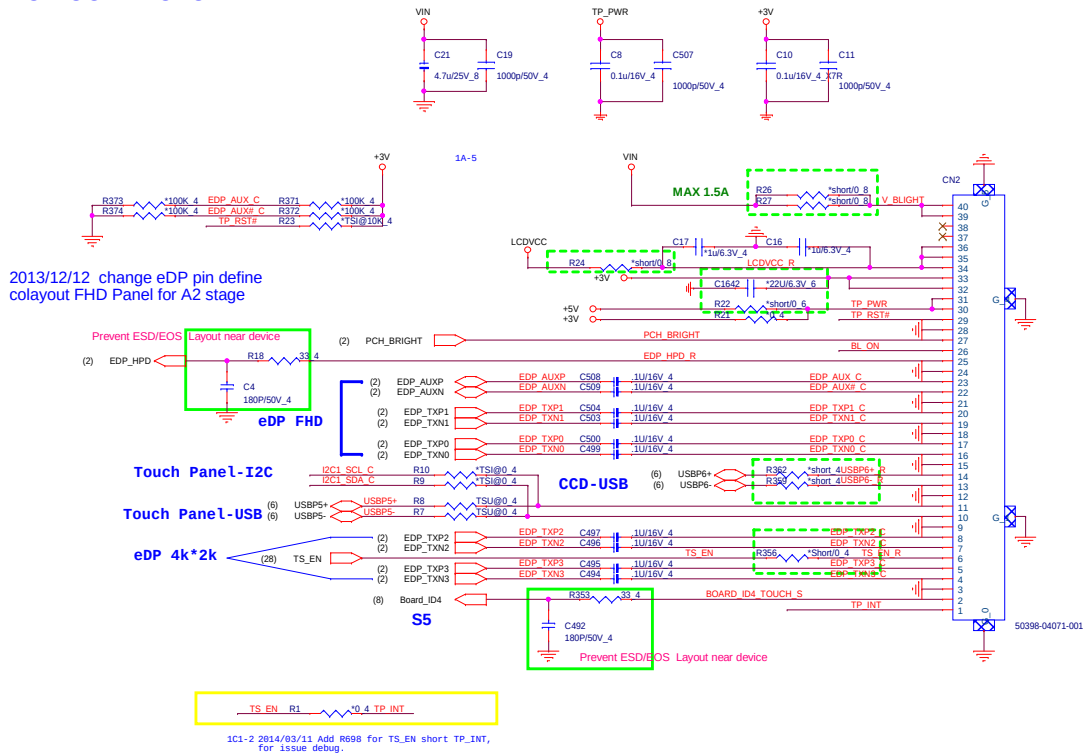
Note:

- 1- C1,C3,C4,C5,C11,C16, C21 should be placed close to chip
- 2- C5 should be X5R material
- 3- R6, R7, R8 should be 75 ohm with +/-1%
- 4- Suggest to connect Pin 29 and Pin 30 to PCH SMBUS for debug purpose.
- 5- This configuration is for internal ROM mode and using embedded LDO mode.

(2,4,6,7,8,9,11,12,13,15,20,21,22,23,24,25,26,27,28,30,31,32,33,34,37,38,39) +3V
(20,21,23,24,26,30,37) +5V



LCD CONNECTOR

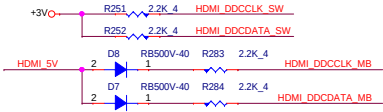
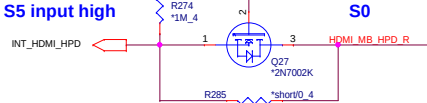


HDMI <HDM>

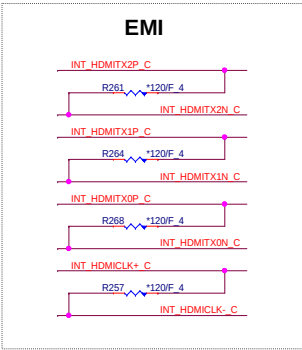
OE_N	DDC_EN	HPD_SINK	Source output	PTN3366 power mode
LOW	HIGH	HIGH	source active	Active mode; DDC active
LOW	LOW	LOW	don't care	Standby mode
HIGH	LOW	don't care	don't care	Ultra low-power mode

From PCH

HDMI-detect

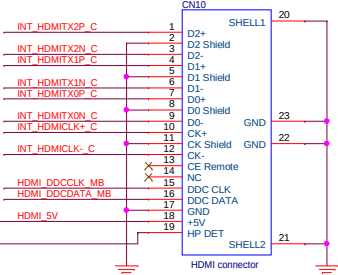


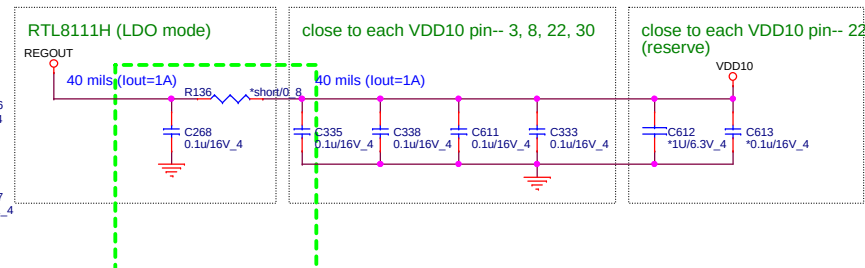
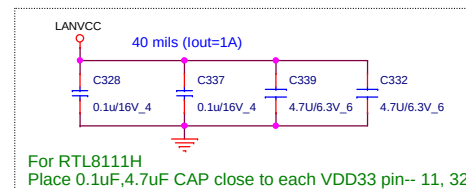
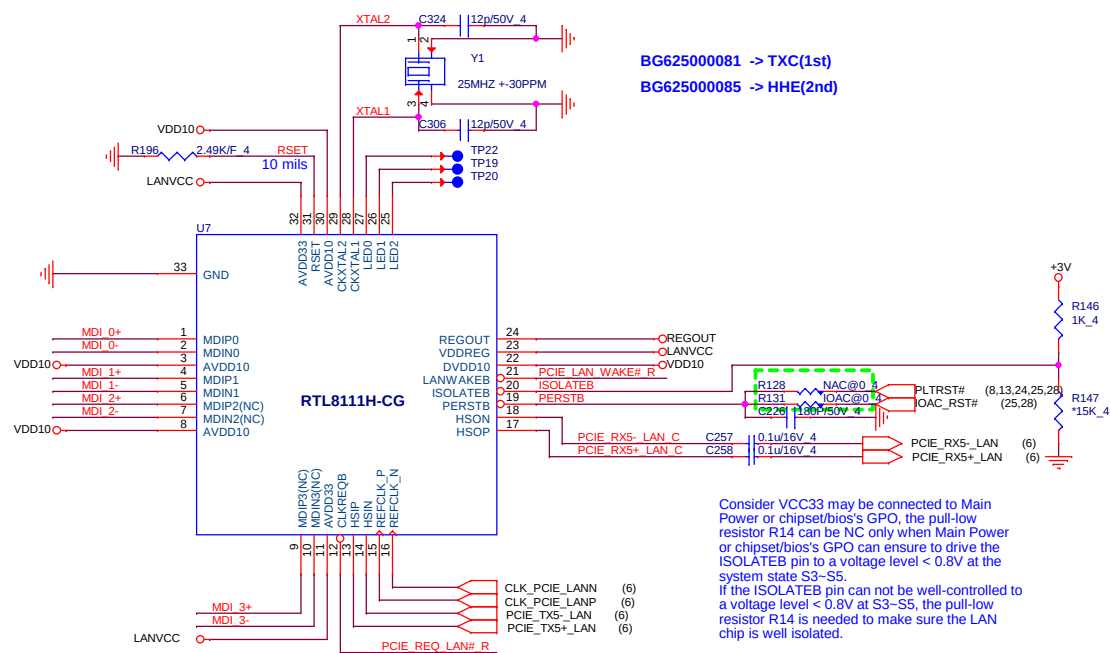
DDS AL002331000



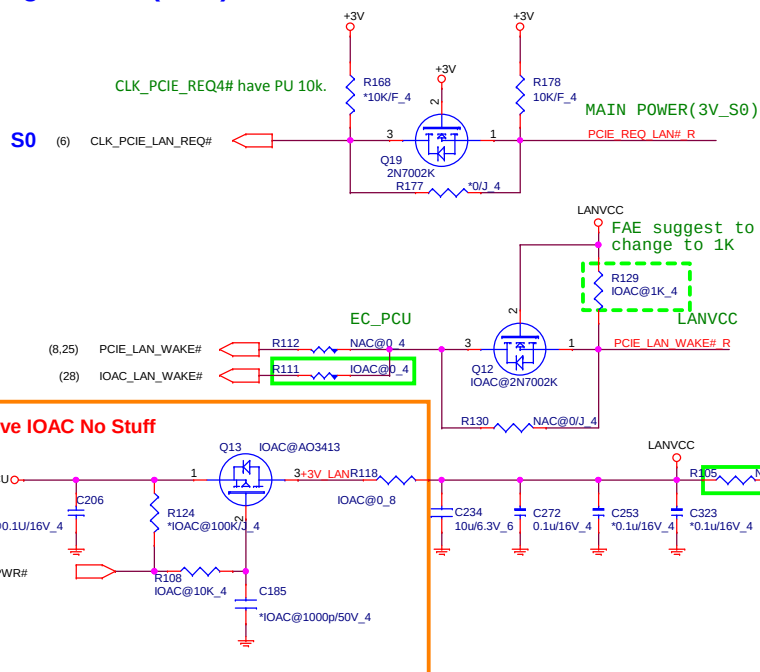
Inputs	EQ1	EQ0	Equalization for 3 Gbit/s
short to GND	short to GND	short to GND	0 dB
short to GND	short to GND	short to Vpp	2 dB
short to Vpp	short to Vpp	short to GND	4 dB
short to Vpp	short to Vpp	short to Vpp	6 dB

HDMI connector



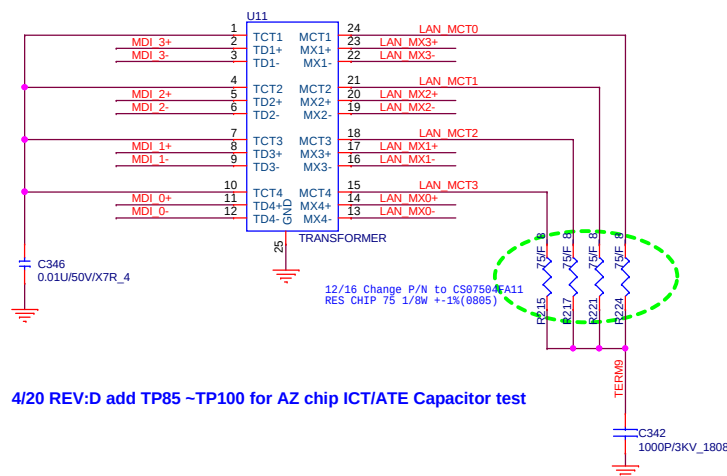


Leakage circuit (MPC)

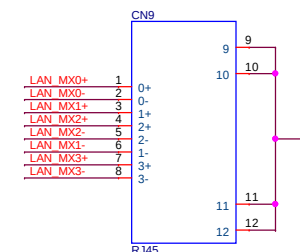


Transformer

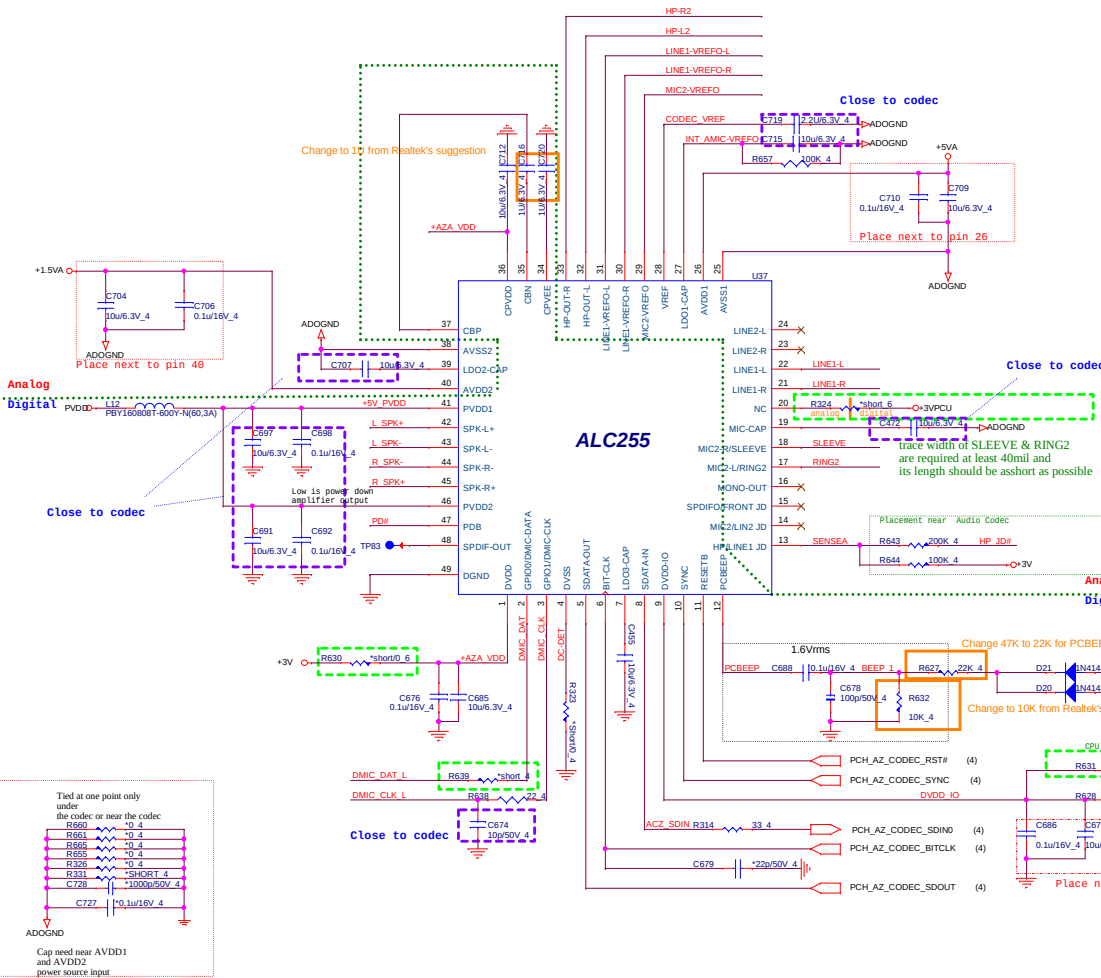
Layout: All termination signal should have 30 mil trace



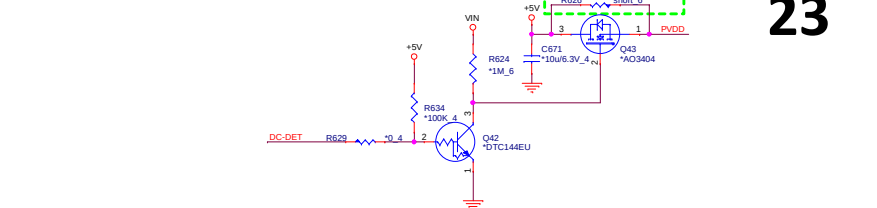
RJ45 Connector



Codec(ADO)

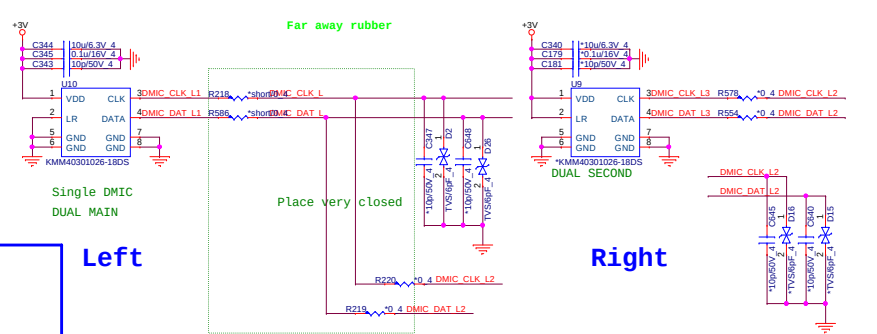


DC-DET circuit(ADO)

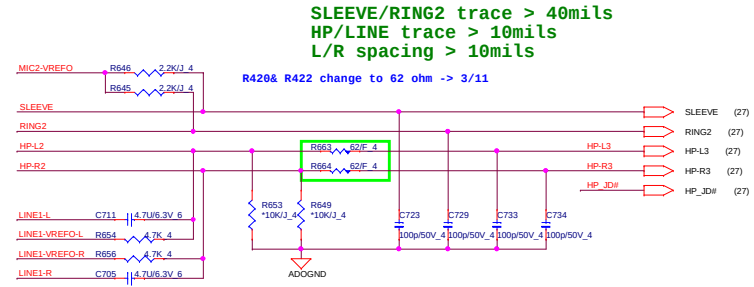


23

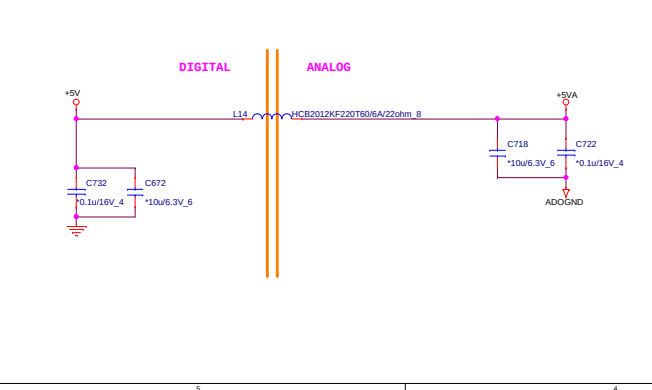
D-Mic (MIC)



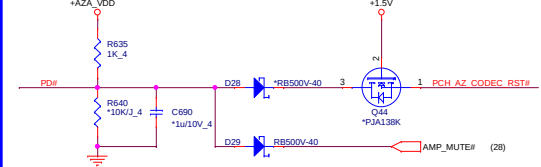
Universal Audio Jack HEADPHONE/MIC/LINE combo (ADO)



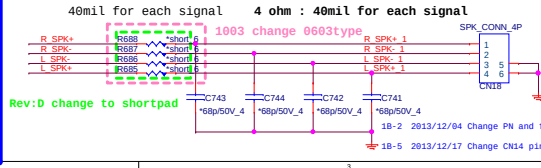
Codec PWR 5V(ADO)



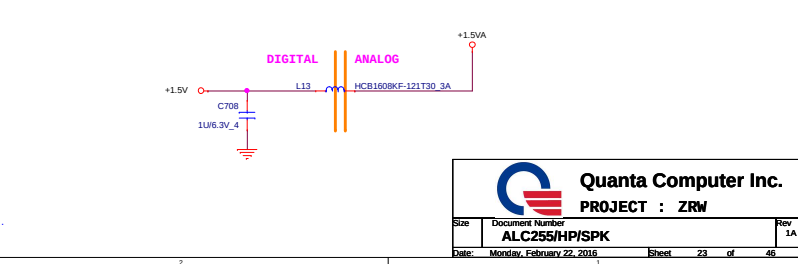
Mute(ADO)



Internal Speaker



Codec PWR 1.5V(ADO)



[illegible]

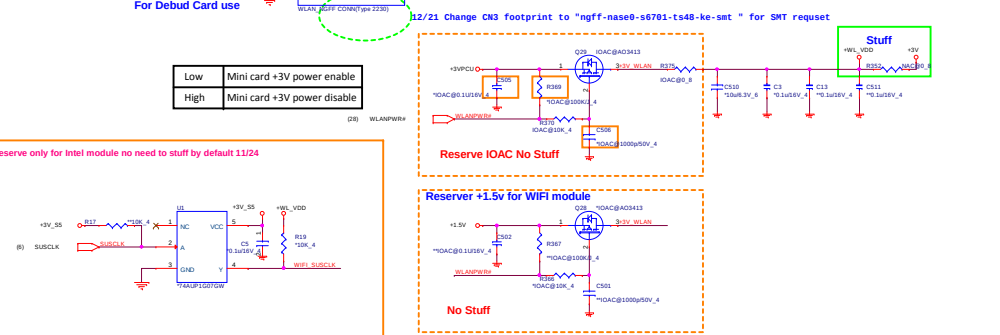
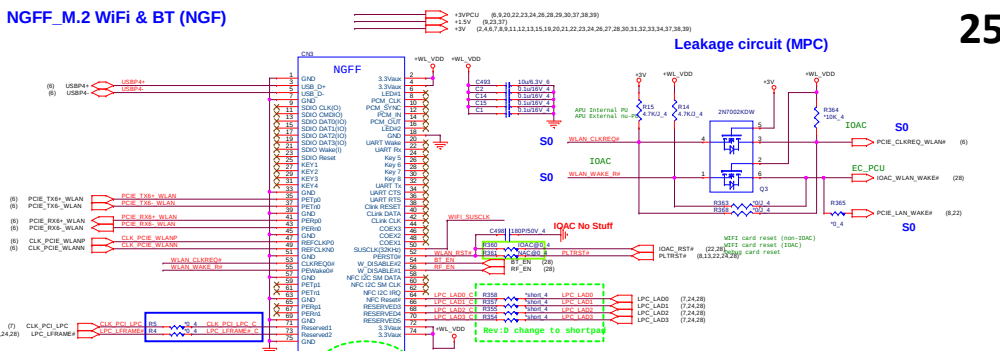
HOLE23
 MB2AA002010
 WLAN NUT
 HOLE7
 *H-TC315C186BC146D146PT
 SSD NUT
 HOLE11
 *H-TC315C186BC146D146PT
 HOLE6
 *H-TC315C186BC146D146PT
 HOLE10
 *H-TC315C186BC146D146PT
 HOLE18
 *HG-TC315BC236D118P2
 SPAD1
 *SPAD-C315
 SPAD2
 *SPAD-C315
 SPAD4
 *H-TC315BC236D118P2
 For GPU sku
 HOLE9
 EV@MB2RQ001010
 HOLE5
 EV@MB2RQ001010
 HOLE15
 MB2AA001010
 HOLE16
 MB2AA001010
 HOLE20
 MB2AA001010
 HOLE21
 *HG-ZBV-3
 HOLE8
 *HG-TC354BC315D118P2
 HOLE19
 *HG-TC354BC315D118P2
 HOLE24
 *p-nb-1
 HOLE51
 *H-C197D197h
 HOLE14
 *H-C118D118h
 HOLE17
 *H-O118X157D118X157h
 12/30 Delete Hole3 & Hole22 for DXF
 12/31 Add for D-Shape Hole
 1/4 Add for DXF
 12/30 Modify Hole1・Hole14・Hole17 to NC

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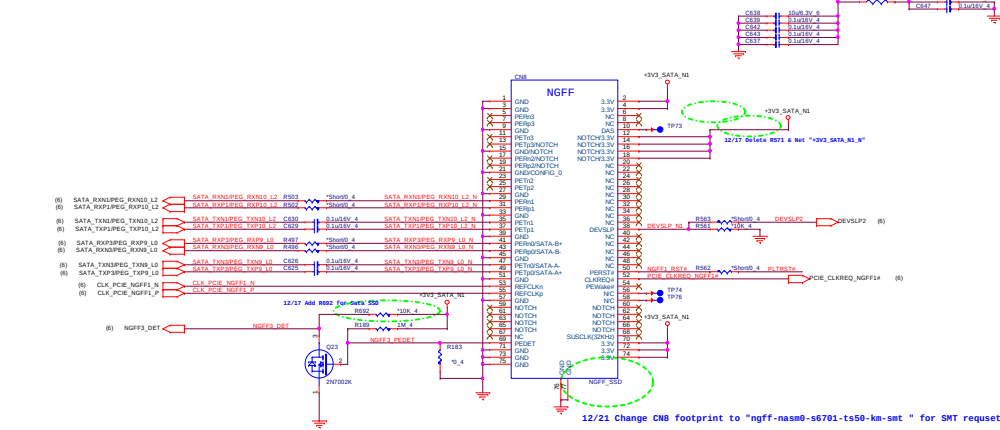
[illegible][illegible]

TPMM 1.2	AL009655K01
TPMM 2.0	AL000650K01

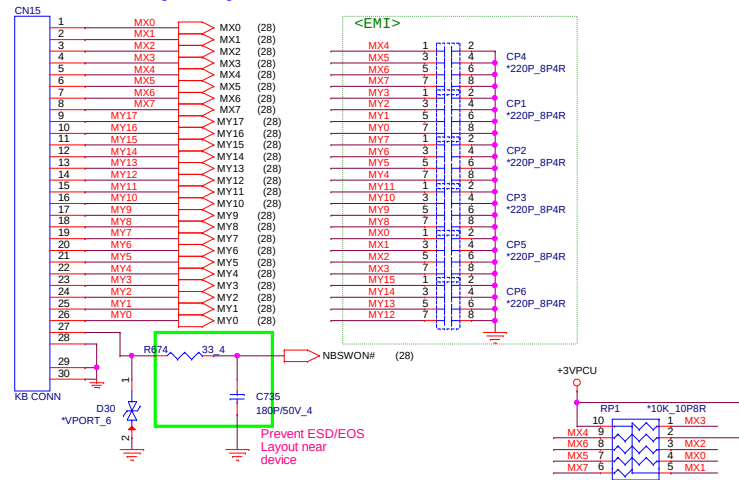
[illegible]



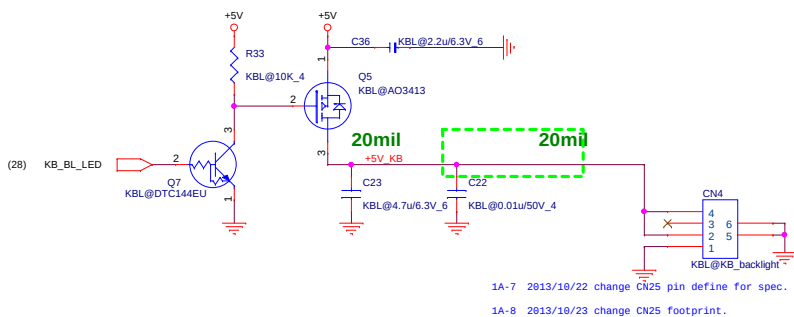
NGFF_M.2 SSD (NGF)



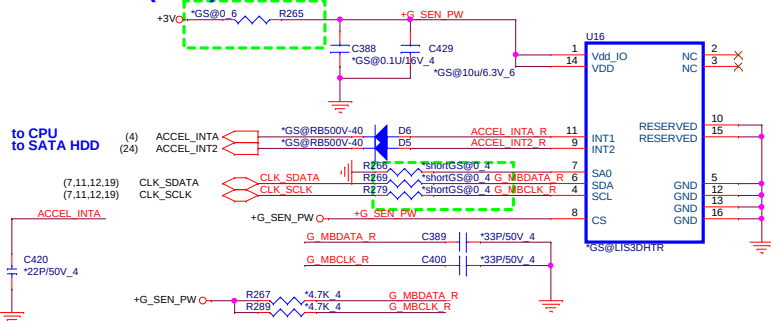
KEYBOARD (KBC)



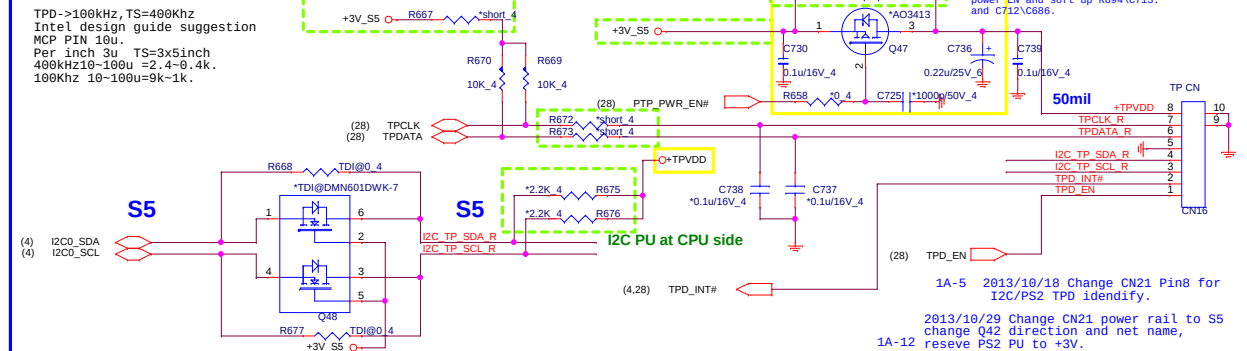
KB_BL LED (KBC)



G-sensor(ACS)

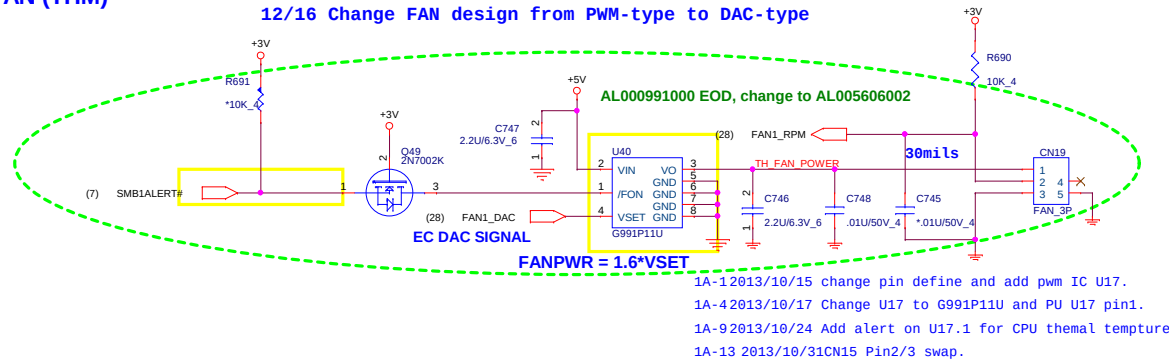


TOUCHPAD BOARD CONN (TPD I2C/PS2 co-lay)



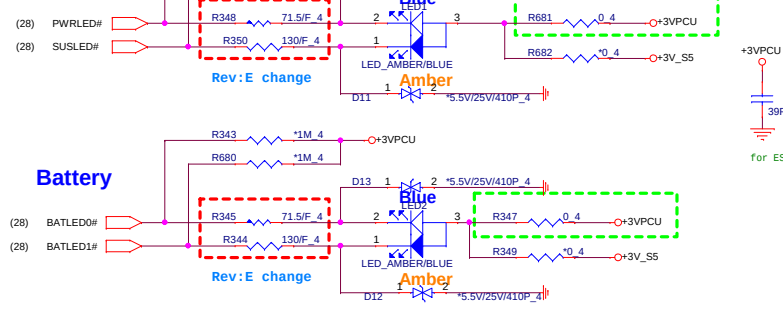
CPU FAN (THM)

12/16 Change FAN design from PWM-type to DAC-type

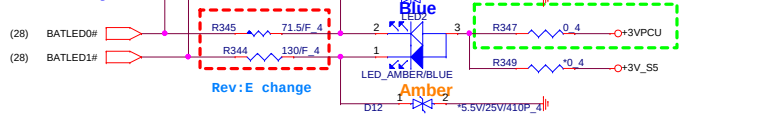


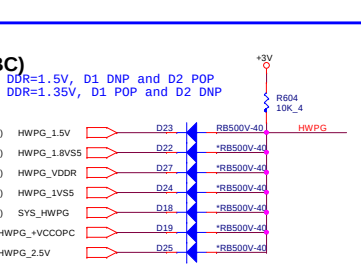
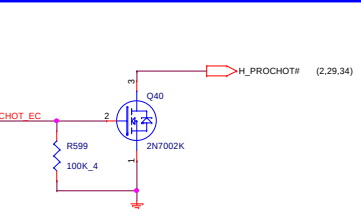
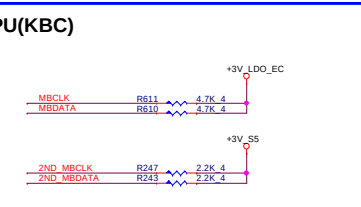
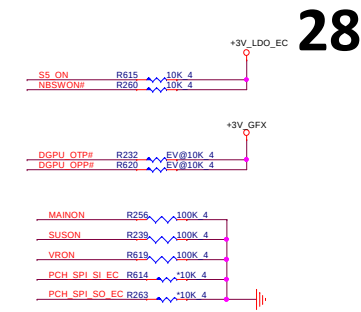
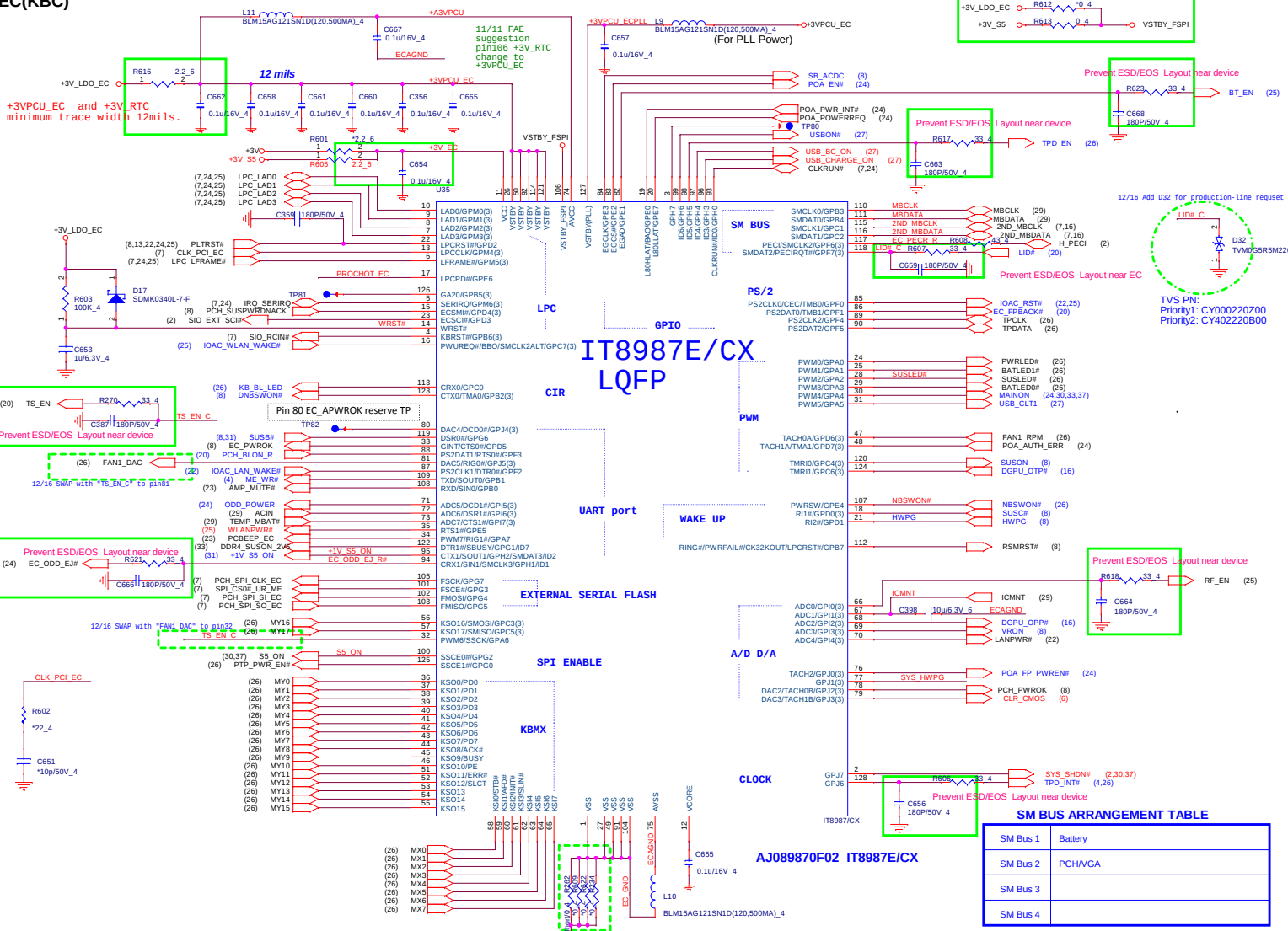
POWER LED(UIF)

Power LED

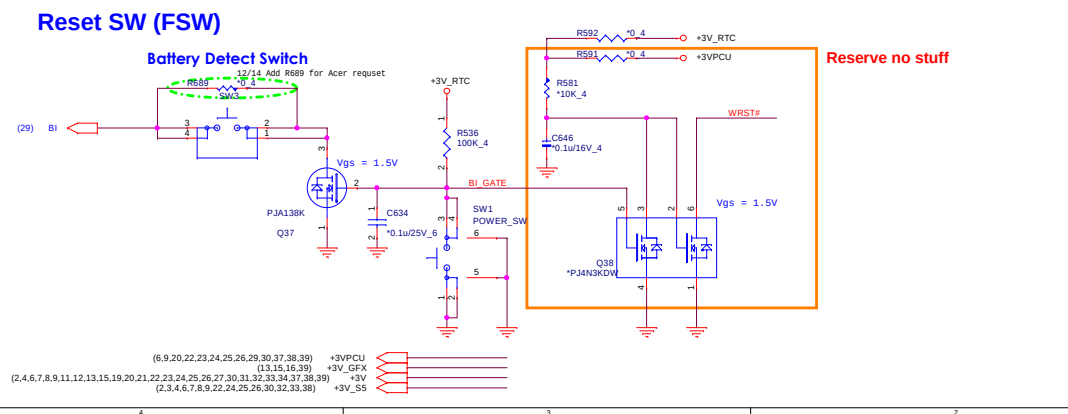
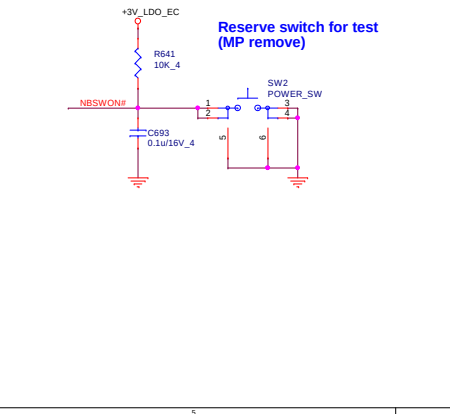


Battery



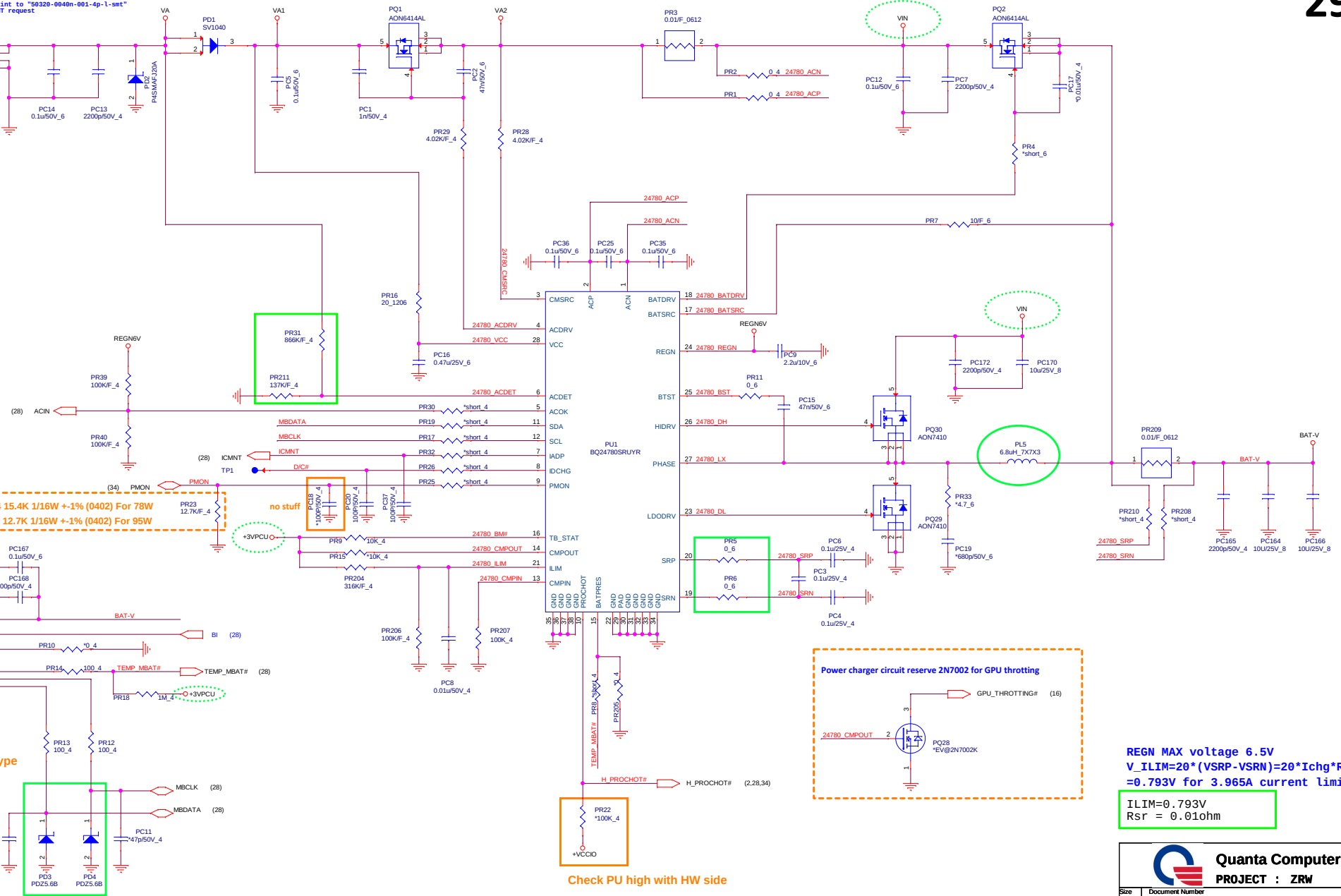


SM BUS ARRANGEMENT TABLE	
SM Bus 1	Battery
SM Bus 2	PCH/VGA
SM Bus 3	
SM Bus 4	



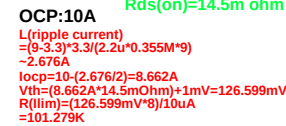
Double Check ADP-In Type

12/22 Change P32 Footprint to "59329-0040n-001-4p-1-smt" & reverse Pin-4 for SMT request

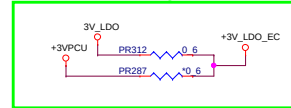


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Power auto recovery

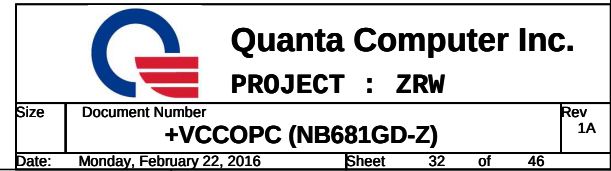


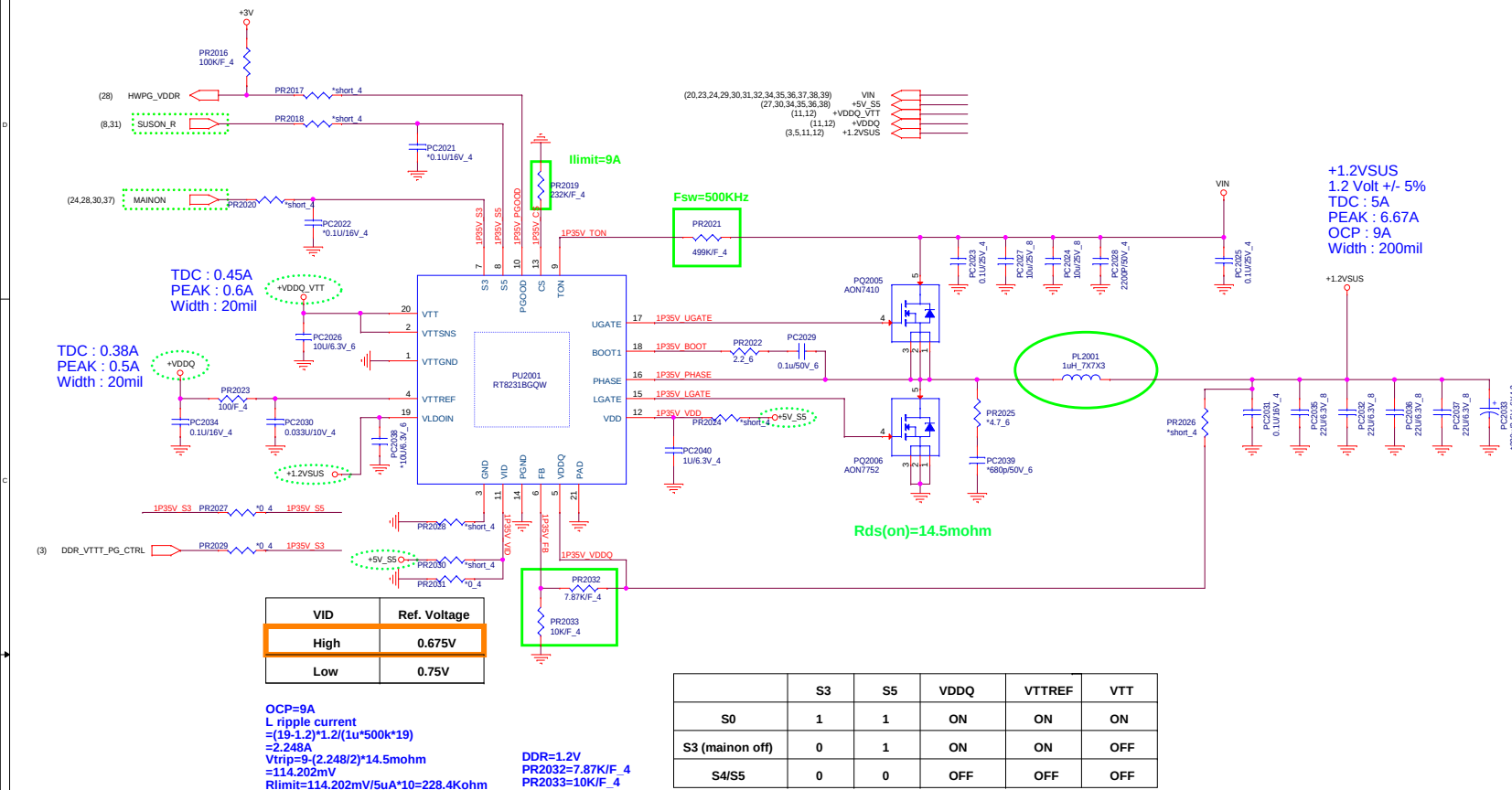
$L(\text{ripple current}) = (9.5) \cdot 5 / (2.2 \cdot 0.3 \cdot 9) = 3.367 \text{ A}$
 $I_{\text{ocp}} = 12 - (3.367/2) = 10.316 \text{ A}$
 $V_{\text{th}} = (10.316 \text{ A} \cdot 14.5 \text{ m}\Omega) + 1 \text{ mV} = 150.589 \text{ mV}$
 $R(\text{Ilim}) = (150.589 \text{ mV} \cdot 8) / 10 \text{ uA} \sim 120.47 \text{ k}\Omega$



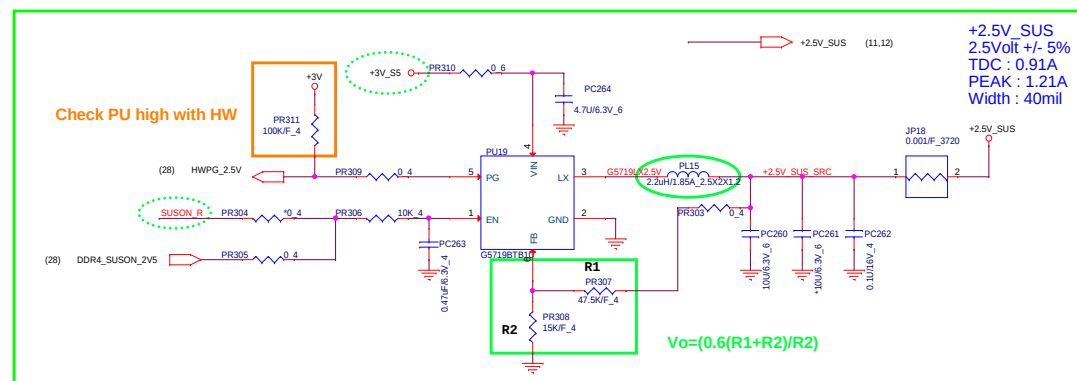


The diagram shows a voltage divider circuit. A +3V_S5 supply is connected to a series combination of resistors R241 (GT3@10K_4) and R240 (*10K_4). The junction between R241 and R240 is connected to ground. A second voltage divider is formed by resistors R238 (*10K_4) and R242 (GT3@10K_4), which are connected in parallel with R241 and R240 respectively. The output of this second divider is connected to two pins, VCCOPC_VID0 and VCCOPC_VID1, which are highlighted in a yellow box.

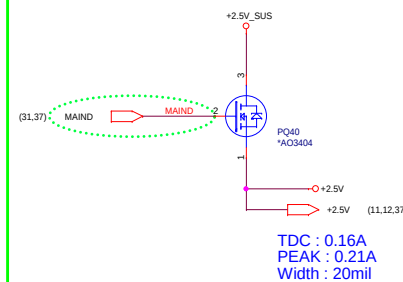


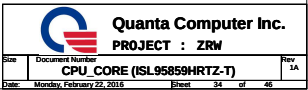


+2.5VSUS Power Rail For DDR4

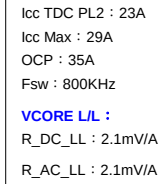


10/26 Reserve +2.5V for DDR4 VDDSPD

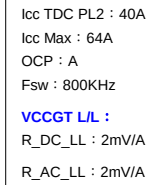




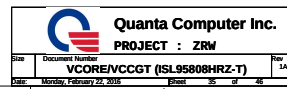
VCORE

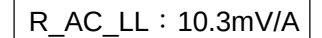


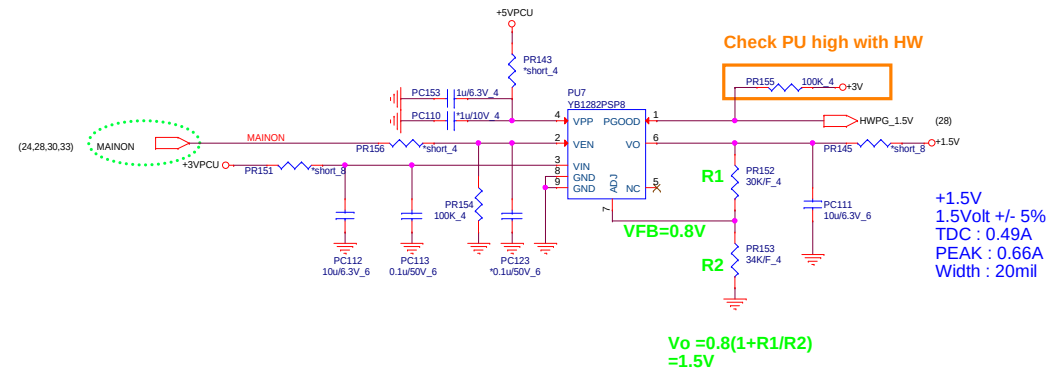
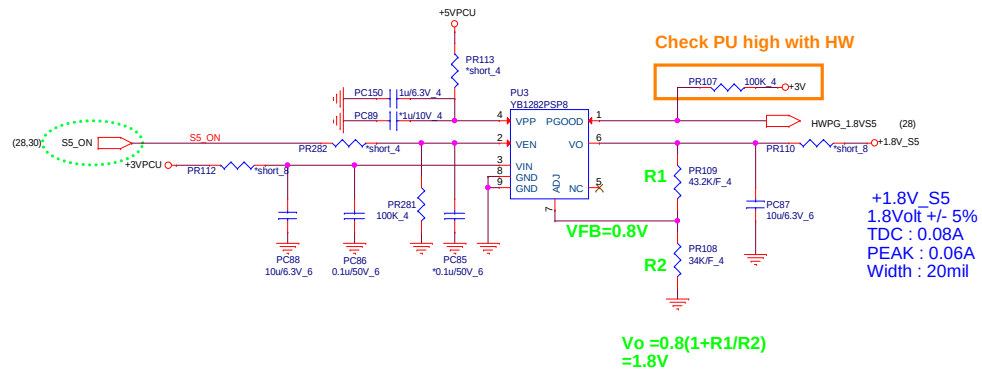
VCCGT



2015/10/2 FAE Suggestion

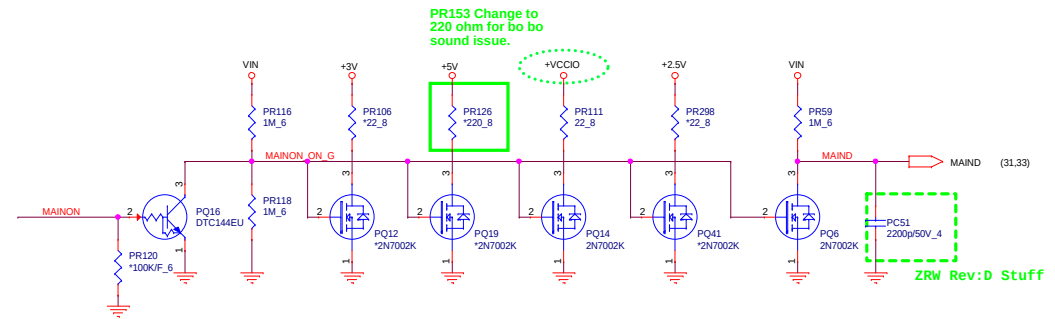
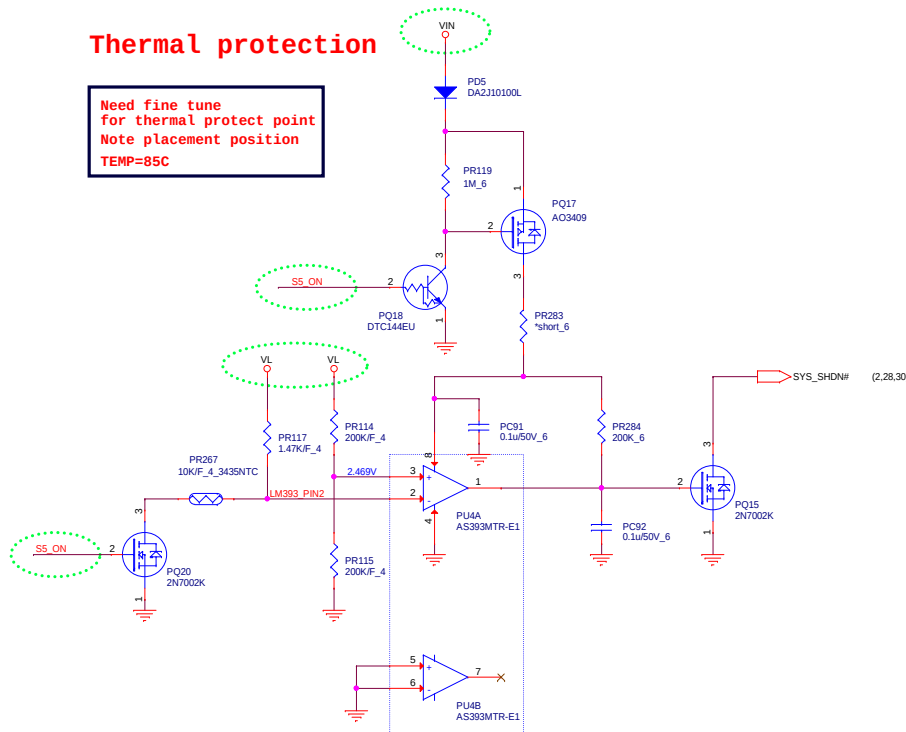






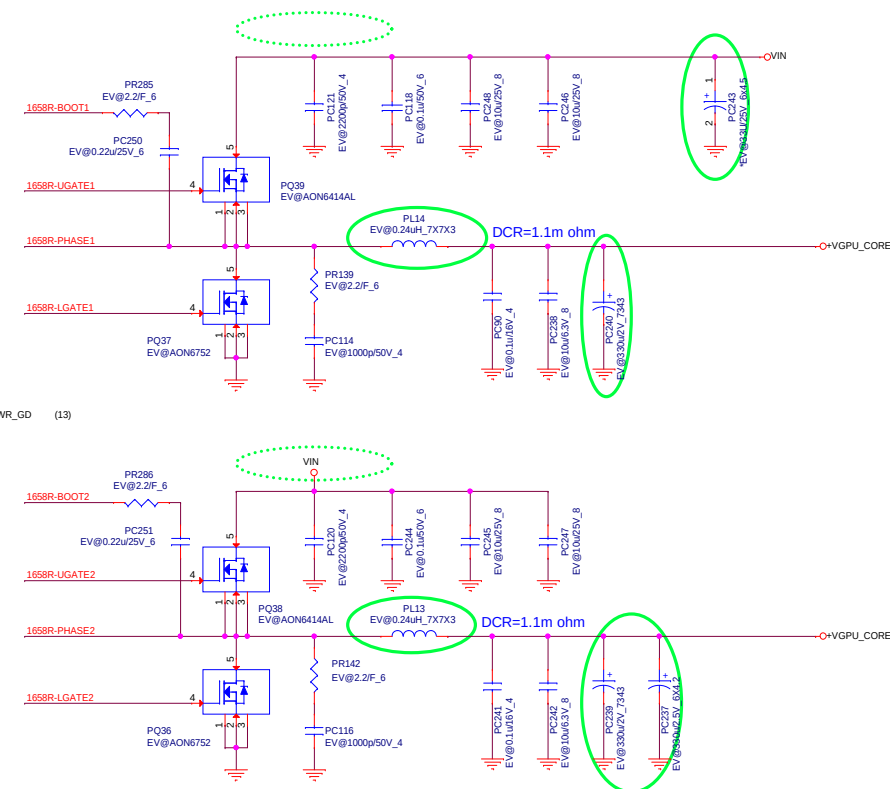
Thermal protection

Need fine tune
for thermal protect point
Note placement position
TEMP=85C



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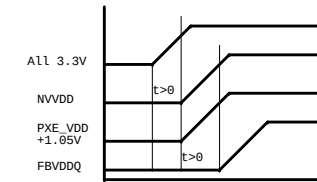
```
+VGPU_CORE
Countinue current:26.5A
Peak current:53A
OCP:72A
FSW:300KHz
L/L=0mV/A
```



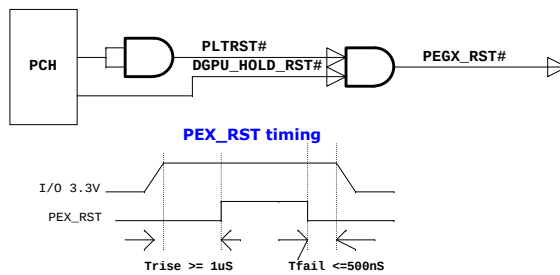
The schematic diagram illustrates the EV@G5335QT2U converter circuit in Pulse-Skipping mode. The circuit is powered by a 5VPCU input and a 3V input. The output is a 1.35V_GFX output. Key components include resistors PR2043, PR2045, PR2047, PR2048, PR2049, PR2052, PR2054, PR2044, PR2046, PR2050, PR2051, PR2053, and capacitors PC2046, PC2047, PC2048, PC2050, PC2051, PC2052, PC2053, PC2054, PC2055, PC2056, PC2057, PC2058, PC2059, PC2060, PC2061, PC2062, and PC2063. The circuit is configured for a switching frequency $F_{sw}=550KHz$ and a load regulation $V_o=0.8 \cdot (R_1+R_2)/R_2 \approx 1.35V$. The output voltage is $V_{FB}=0.8V$.

+1.35V_GFX
1.35 Volt +/- 5%
TDC : 4.67A
PEAK : 6.22A
Width : 200mil

$$V_o = 0.8 \cdot (R_1 + R_2) / R_2 = 1.35V$$

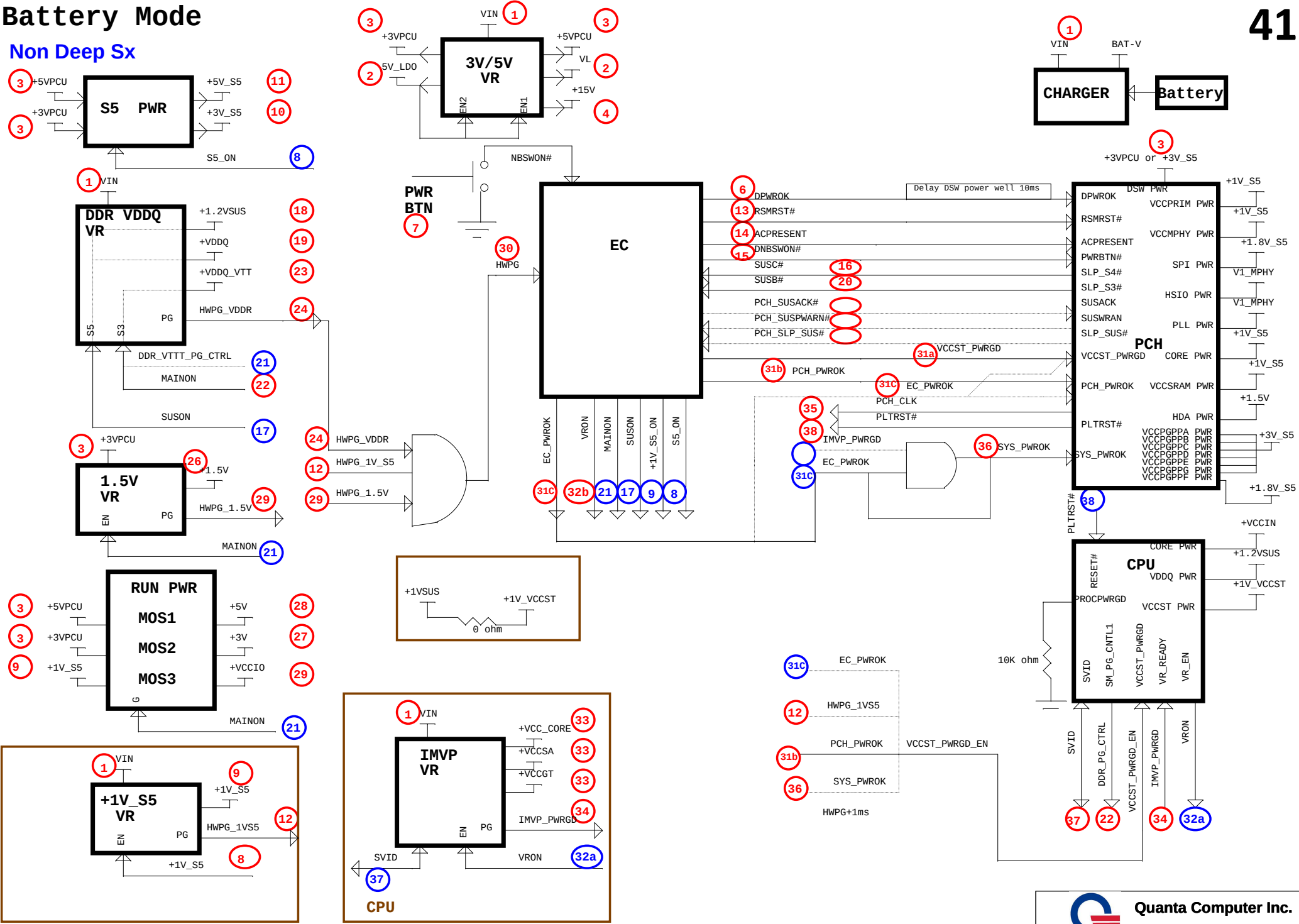


VGA Reset

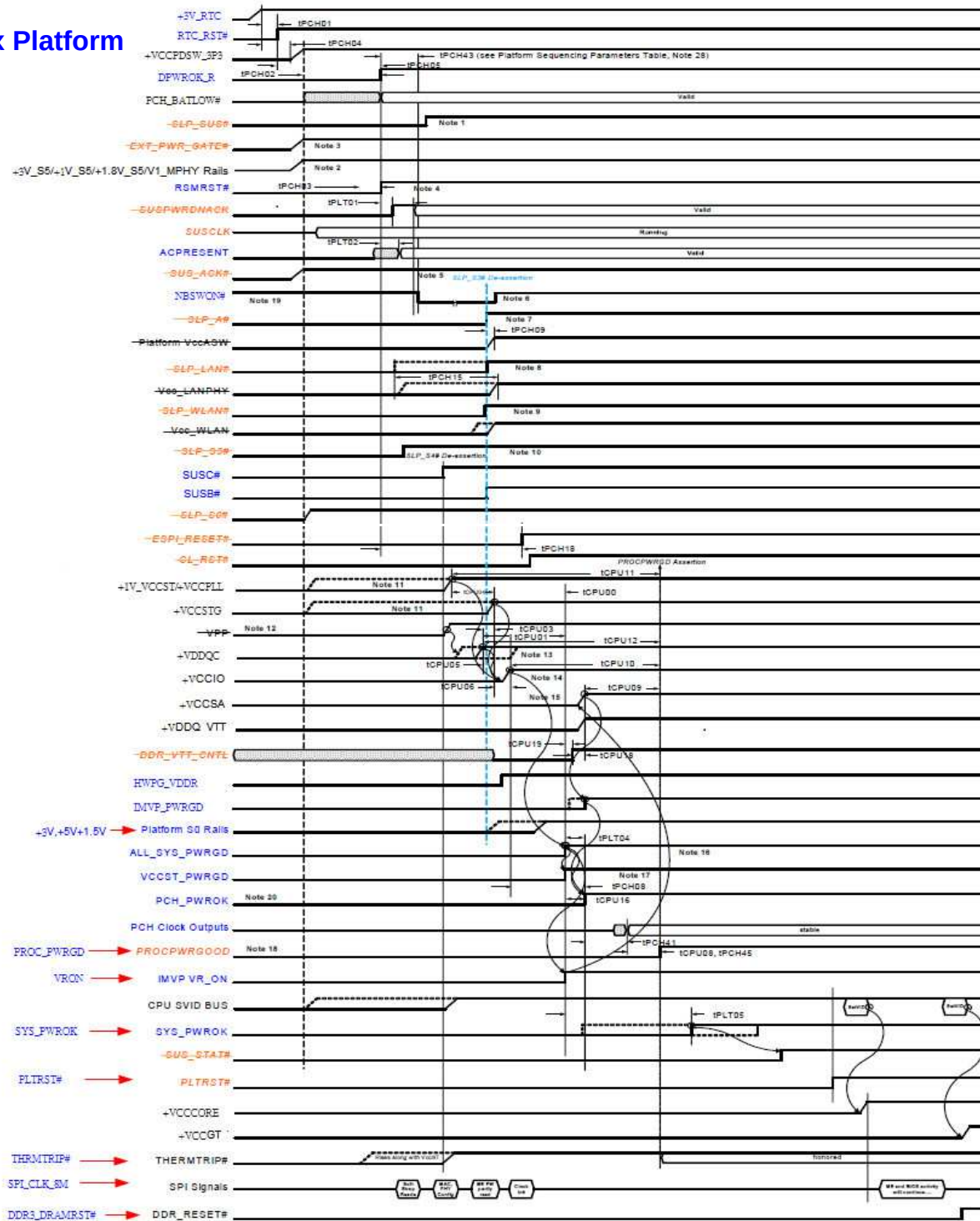


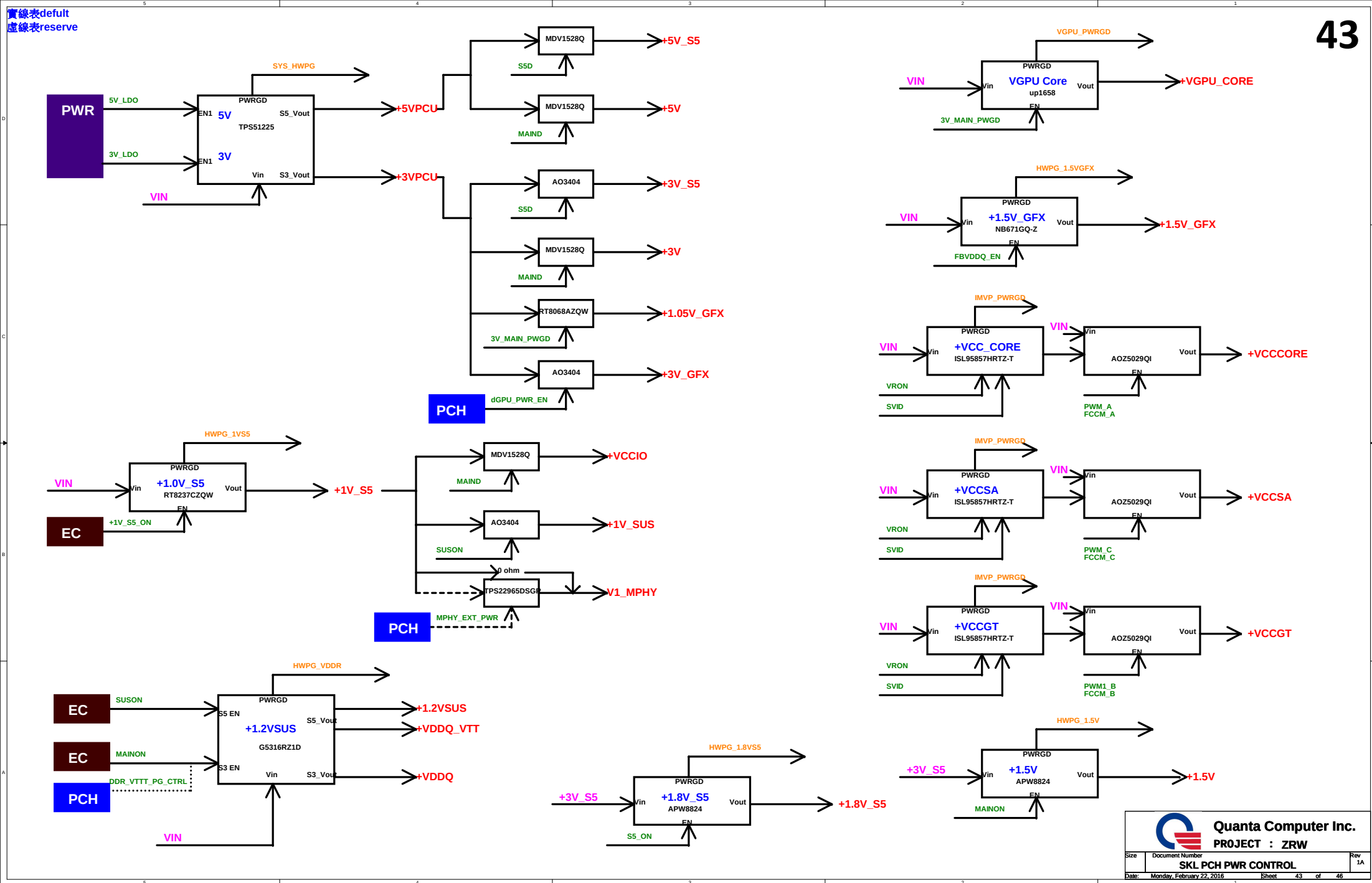
Battery Mode

Non Deep Sx

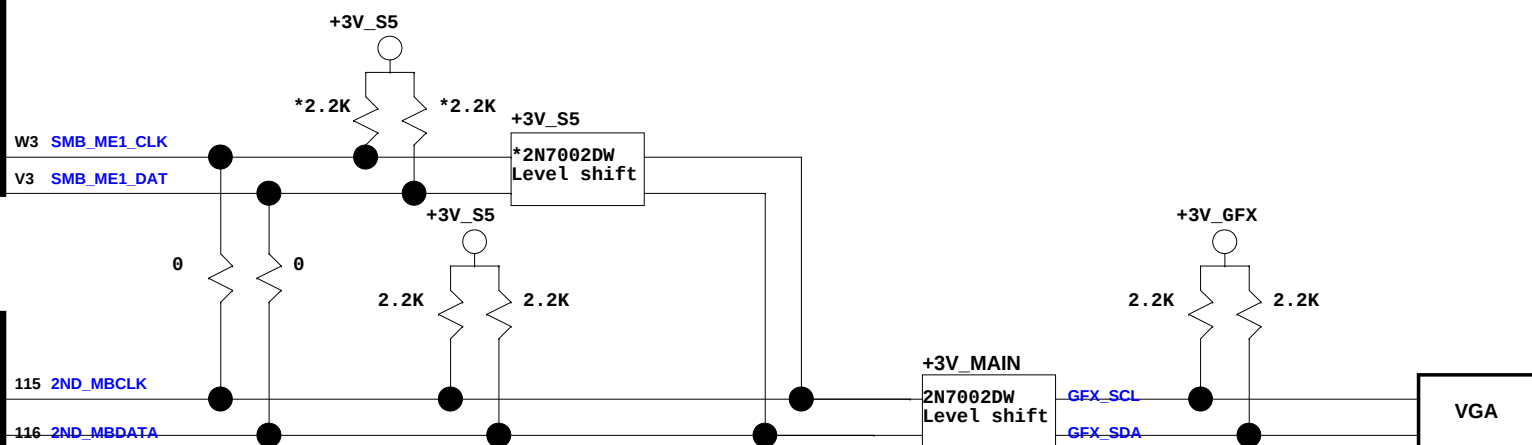
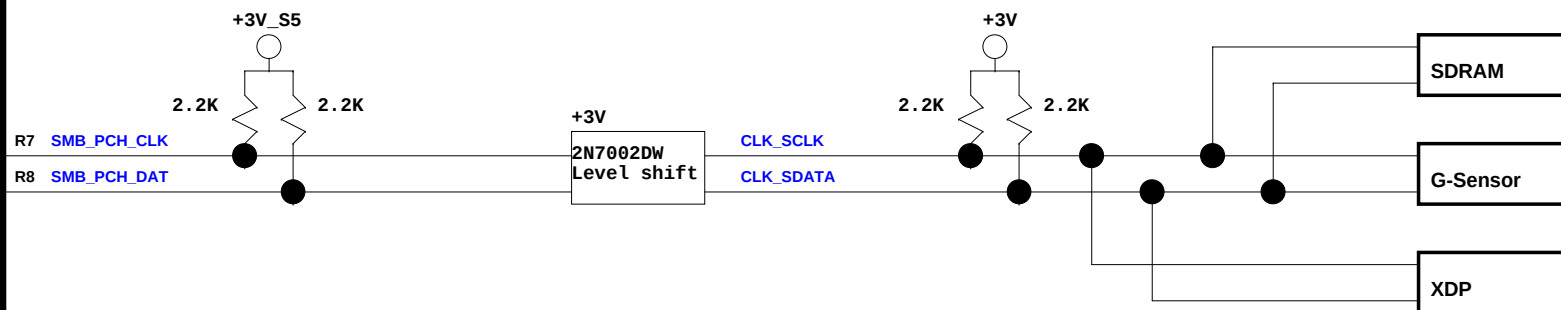


Skylake U Non-Deep Sx Platform Power on sequence





Skylake U

EC
IT8987CX